

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

DESCRIPTION

The MH8S64AKD is 8388608 - word by 64-bit Synchronous DRAM module. This consists of eight industry standard 8Mx8 Synchronous DRAMs in TSOP and one industry standard EEPROM in TSSOP.

The mounting of TSOP on a card edge Dual Inline package provides any application where high densities and large quantities of memory are required.

This is a socket type - memory modules, suitable for easy interchange or addition of modules.

- Utilizes industry standard 8M x 8 Synchronous DRAMs TSOP and industry standard EEPROM in TSSOP
- 144-pin (72-pin dual in-line package)
- single 3.3V±0.3V power supply
- Clock frequency 125MHz/100MHz/83MHz
- Fully synchronous operation referenced to clock rising edge
- Dual bank operation controlled by BA0,1(Bank Address)
- /CAS latency- 2/3(programmable)
- Burst length- 1/2/4/8(programmable)
- Burst type- sequential / interleave(programmable)
- Column access - random
- Auto precharge / All bank precharge controlled by A10
- Auto refresh and Self refresh
- 4096 refresh cycle /64ms
- LVTTTL Interface

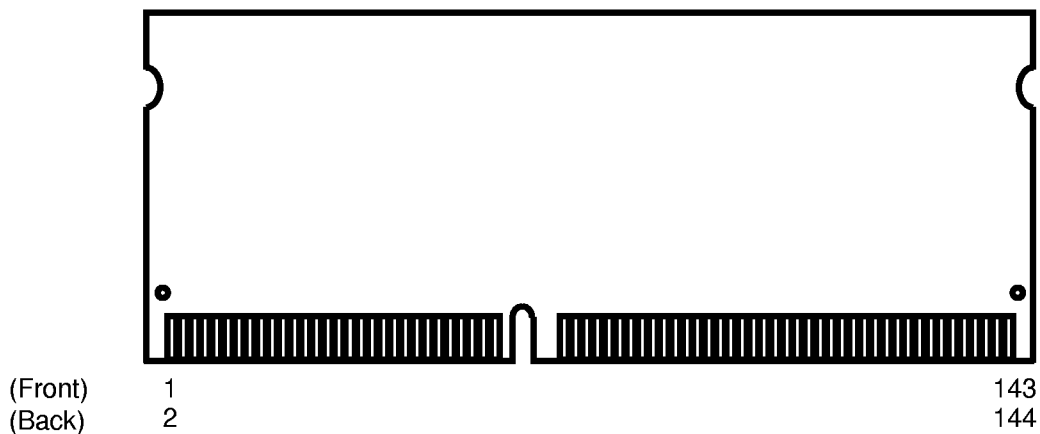
FEATURES

	Frequency	CLK Access Time (Component SDRAM)
-8,-8L	100MHz	6ns(CL=3)
-10,-10L	100MHz	8ns(CL=3)

APPLICATION

main memory or graphic memory in computer systems

PCB Outline



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PIN CONFIGURATION

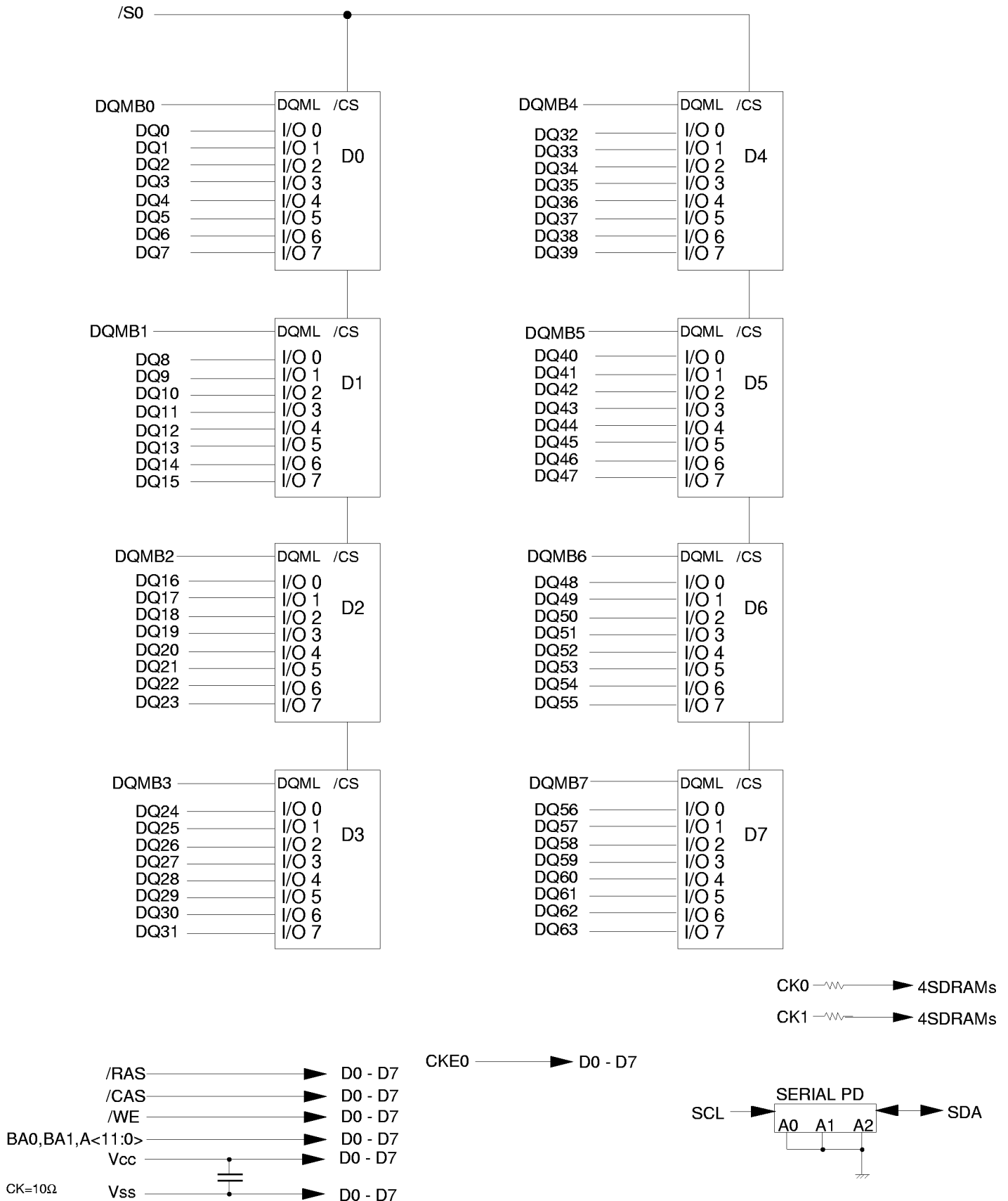
PIN Number	Front side Pin Name	PIN Number	Back side Pin Name	PIN Number	Front side Pin Name	PIN Number	Back side Pin Name
1	Vss	2	Vss	73	NC	74	CK1
3	DQ0	4	DQ32	75	Vss	76	Vss
5	DQ1	6	DQ33	77	NC	78	NC
7	DQ2	8	DQ34	79	NC	80	NC
9	DQ3	10	DQ35	81	Vcc	82	Vcc
11	Vcc	12	Vcc	83	DQ16	84	DQ48
13	DQ4	14	DQ36	85	DQ17	86	DQ49
15	DQ5	16	DQ37	87	DQ18	88	DQ50
17	DQ6	18	DQ38	89	DQ19	90	DQ51
19	DQ7	20	DQ39	91	Vss	92	Vss
21	Vss	22	Vss	93	DQ20	94	DQ52
23	DQMB0	24	DQMB4	95	DQ21	96	DQ53
25	DQMB1	26	DQMB5	97	DQ22	98	DQ54
27	Vcc	28	Vcc	99	DQ23	100	DQ55
29	A0	30	A3	101	Vcc	102	Vcc
31	A1	32	A4	103	A6	104	A7
33	A2	34	A5	105	A8	106	BA0
35	Vss	36	Vss	107	Vss	108	Vss
37	DQ8	38	DQ40	109	A9	110	BA1
39	DQ9	40	DQ41	111	A10	112	A11
41	DQ10	42	DQ42	113	Vcc	114	Vcc
43	DQ11	44	DQ43	115	DQMB2	116	DQMB6
45	Vcc	46	Vcc	117	DQMB3	118	DQMB7
47	DQ12	48	DQ44	119	Vss	120	Vss
49	DQ13	50	DQ45	121	DQ24	122	DQ56
51	DQ14	52	DQ46	123	DQ25	124	DQ57
53	DQ15	54	DQ47	125	DQ26	126	DQ58
55	Vss	56	Vss	127	DQ27	128	DQ59
57	NC	58	NC	129	Vcc	130	Vcc
59	NC	60	NC	131	DQ28	132	DQ60
61	CK0	62	CKE	133	DQ29	134	DQ61
63	Vcc	64	Vcc	135	DQ30	136	DQ62
65	/RAS	66	/CAS	137	DQ31	138	DQ63
67	/WE	68	NC	139	Vss	140	Vss
69	/S	70	NC	141	SDA	142	SCL
71	NC	72	NC	143	Vcc	144	Vcc

NC = No Connection

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Block Diagram



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PIN FUNCTION

CK (CK0 ~ CK1)	Input	Master Clock:All other inputs are referenced to the rising edge of CK
CKE0	Input	Clock Enable:CKE controls internal clock.When CKE is low,internal clock for the following cycle is ceased. CKE is also used to select auto / self refresh. After self refresh mode is started, CKE E becomes asynchronous input.Self refresh is maintained as long as CKE is low.
/S0	Input	Chip Select: When /S is high,any command means No Operation.
/RAS,/CAS,/WE	Input	Combination of /RAS,/CAS,/WE defines basic commands.
A0-11	Input	A0-11 specify the Row/Column Address in conjunction with BA.The Row Address is specified by A0-11.The Column Address is specified by A0-8.A10 is also used to indicate precharge option.When A10 is high at a read / write command, an auto precharge is performed. When A10 is high at a precharge command, both banks are precharged.
BA0,1	Input	Bank Address:BA0,1 is not simply BA.BA specifies the bank to which a command is applied.BA0,1 must be set with ACT,PRE,READ,WRITE commands
DQ0-63	Input/Output	Data In and Data out are referenced to the rising edge of CK
DQMB0-7	Input	Din Mask/Output Disable:When DQMB is high in burst write.Din for the current cycle is masked.When DQMB is high in burst read,Dout is disabled at the next but one cycle.
Vdd,Vss	Power Supply	Power Supply for the memory mounted module.
SCL	Input	Serial clock for serial PD
SDA	Output	Serial data for serial PD

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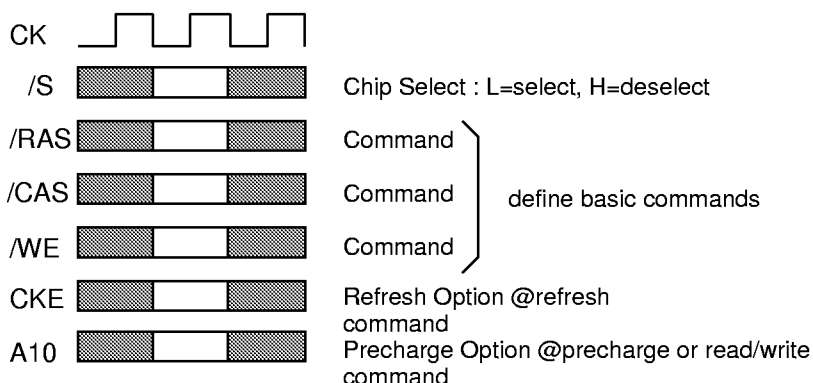
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BASIC FUNCTIONS

The MH8S64AKD provides basic functions, bank(row) activate, burst read / write, bank(row) precharge, and auto / self refresh.

Each command is defined by control signals of /RAS, /CAS and /WE at CK rising edge. In addition to 3 signals, /S, CKE and A10 are used as chip select, refresh option, and precharge option, respectively.

To know the detailed definition of commands please see the command truth table.



Activate(ACT) [/RAS =L, /CAS = /WE =H]

ACT command activates a row in an idle bank indicated by BA0,1.

Read(READ) [/RAS =H, /CAS =L, /WE =H]

READ command starts burst read from the active bank indicated by BA0,1. First output data appears after /CAS latency. When A10 =H at this command, the bank is deactivated after the burst read(auto-precharge, **READA**).

Write(WRITE) [/RAS =H, /CAS = /WE =L]

WRITE command starts burst write to the active bank indicated by BA0,1. Total data length to be written is set by burst length. When A10 =H at this command, the bank is deactivated after the burst write(auto-precharge, **WRITEA**).

Precharge(PRE) [/RAS =L, /CAS =H, /WE =L]

PRE command deactivates the active bank indicated by BA0,1. This command also terminates burst read / write operation. When A10 =H at this command, both banks are deactivated(precharge all, **PREA**).

Auto-Refresh(REFA) [/RAS =/CAS =L, /WE =CKE =H]

REFA command starts auto-refresh cycle. Refresh address including bank address are generated internally. After this command, the banks are precharged automatically.

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COMMAND TRUTH TABLE

COMMAND	MNEMONIC	CKE n-1	CKE n	/CS	/RAS	/CAS	/WE	BA0,1	A11	A10	A0-9
Deselect	DESEL	H	X	H	X	X	X	X	X	X	X
No Operation	NOP	H	X	L	H	H	H	X	X	X	X
Row Address Entry & Bank Activate	ACT	H	X	L	L	H	H	V	V	V	V
Single Bank Precharge	PRE	H	X	L	L	H	L	V	X	L	X
Precharge All Banks	PREA	H	X	L	L	H	L	X	X	H	X
Column Address Entry & Write	WRITE	H	X	L	H	L	L	V	X	L	V
Column Address Entry & Write with Auto- Precharge	WRITEA	H	X	L	H	L	L	V	X	H	V
Column Address Entry & Read	READ	H	X	L	H	L	H	V	X	L	V
Column Address Entry & Read with Auto- Precharge	READA	H	X	L	H	L	H	V	X	H	V
Auto-Refresh	REFA	H	H	L	L	L	H	X	X	X	X
Self-Refresh Entry	REFS	H	L	L	L	L	H	X	X	X	X
Self-Refresh Exit	REFSX	L	H	H	X	X	X	X	X	X	X
		L	H	L	H	H	H	X	X	X	X
Burst Terminate	TBST	H	X	L	H	H	L	X	X	X	X
Mode Register Set	MRS	H	X	L	L	L	L	L	L	L	V*1

H=High Level, L=Low Level, V=Valid, X=Don't Care, n=CLK cycle number

NOTE:

1. A7-A9 =0, A0-A6 =Mode Address

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FUNCTION TRUTH TABLE

Current State	/S	/RAS	/CAS	/WE	Address	Command	Action
IDLE	H	X	X	X	X	DESEL	NOP
	L	H	H	H	X	NOP	NOP
	L	H	H	L	BA	TBST	ILLEGAL*2
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL*2
	L	L	H	H	BA,RA	ACT	Bank Active,Latch RA
	L	L	H	L	BA,A10	PRE/PREA	NOP*4
	L	L	L	H	X	REFA	Auto-Refresh*5
	L	L	L	L	Op-Code, Mode-Add	MRS	Mode Register Set*5
ROW ACTIVE	H	X	X	X	X	DESEL	NOP
	L	H	H	H	X	NOP	NOP
	L	H	H	L	BA	TBST	NOP
	L	H	L	H	BA,CA,A10	READ/READA	Begin Read,Latch CA, Determine Auto-Precharge
	L	H	L	L	BA,CA,A10	WRITE/ WRITEA	Begin Write,Latch CA, Determine Auto-Precharge
	L	L	H	H	BA,RA	ACT	Bank Active/ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	Precharge/Precharge All
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
READ	H	X	X	X	X	DESEL	NOP(Continue Burst to END)
	L	H	H	H	X	NOP	NOP(Continue Burst to END)
	L	H	H	L	BA	TBST	Terminate Burst
	L	H	L	H	BA,CA,A10	READ/READA	Terminate Burst,Latch CA, Begin New Read,Determine Auto-Precharge*3
	L	H	L	L	BA,CA,A10	WRITE/WRITEA	Terminate Burst,Latch CA, Begin Write,Determine Auto- Precharge*3
	L	L	H	H	BA,RA	ACT	Bank Active/ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	Terminate Burst,Precharge
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL

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FUNCTION TRUTH TABLE(continued)

Current State	/S	/RAS	/CAS	/WE	Address	Command	Action
WRITE	H	X	X	X	X	DESEL	NOP(Continue Burst to END)
	L	H	H	H	X	NOP	NOP(Continue Burst to END)
	L	H	H	L	BA	TBST	Terminate Burst
	L	H	L	H	BA,CA,A10	READ/READA	Terminate Burst,Latch CA, Begin Read,Determine Auto-Precharge*3
	L	H	L	L	BA,CA,A10	WRITE/ WRITEA	Terminate Burst,Latch CA, Begin Write,Determine Auto-Precharge*3
	L	L	H	H	BA,RA	ACT	Bank Active/ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	Terminate Burst,Precharge
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
READ with AUTO PRECHARGE	H	X	X	X	X	DESEL	NOP(Continue Burst to END)
	L	H	H	H	X	NOP	NOP(Continue Burst to END)
	L	H	H	L	BA	TBST	ILLEGAL
	L	H	L	H	BA,CA,A10	READ/READA	ILLEGAL
	L	H	L	L	BA,CA,A10	WRITE/ WRITEA	ILLEGAL
	L	L	H	H	BA,RA	ACT	Bank Active/ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL*2
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
WRITE with AUTO PRECHARGE	H	X	X	X	X	DESEL	NOP(Continue Burst to END)
	L	H	H	H	X	NOP	NOP(Continue Burst to END)
	L	H	H	L	BA	TBST	ILLEGAL
	L	H	L	H	BA,CA,A10	READ/READA	ILLEGAL
	L	H	L	L	BA,CA,A10	WRITE/ WRITEA	ILLEGAL
	L	L	H	H	BA,RA	ACT	Bank Active/ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL*2
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL

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FUNCTION TRUTH TABLE(continued)

Current State	/S	/RAS	/CAS	/WE	Address	Command	Action
PRE - CHARGING	H	X	X	X	X	DESEL	NOP(Idle after tRP)
	L	H	H	H	X	NOP	NOP(Idle after tRP)
	L	H	H	L	BA	TBST	ILLEGAL*2
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL*2
	L	L	H	H	BA,RA	ACT	ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	NOP*4(Idle after tRP)
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
ROW ACTIVATING	H	X	X	X	X	DESEL	NOP(Row Active after tRCD)
	L	H	H	H	X	NOP	NOP(Row Active after tRCD)
	L	H	H	L	BA	TBST	ILLEGAL*2
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL*2
	L	L	H	H	BA,RA	ACT	ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL*2
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
WRITE RE- COVERING	H	X	X	X	X	DESEL	NOP
	L	H	H	H	X	NOP	NOP
	L	H	H	L	BA	TBST	ILLEGAL*2
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL*2
	L	L	H	H	BA,RA	ACT	ILLEGAL*2
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL*2
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL

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FUNCTION TRUTH TABLE(continued)

Current State	/S	/RAS	/CAS	/WE	Address	Command	Action
RE-FRESHING	H	X	X	X	X	DESEL	NOP(Idle after tRC)
	L	H	H	H	X	NOP	NOP(Idle after tRC)
	L	H	H	L	BA	TBST	ILLEGAL
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL
	L	L	H	H	BA,RA	ACT	ILLEGAL
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL
MODE REGISTER SETTING	H	X	X	X	X	DESEL	NOP(Idle after tRSC)
	L	H	H	H	X	NOP	NOP(Idle after tRSC)
	L	H	H	L	BA	TBST	ILLEGAL
	L	H	L	X	BA,CA,A10	READ/WRITE	ILLEGAL
	L	L	H	H	BA,RA	ACT	ILLEGAL
	L	L	H	L	BA,A10	PRE/PREA	ILLEGAL
	L	L	L	H	X	REFA	ILLEGAL
	L	L	L	L	Op-Code, Mode-Add	MRS	ILLEGAL

ABBREVIATIONS:

H = High Level, L = Low Level, X = Don't Care

BA = Bank Address, RA = Row Address, CA = Column Address, NOP = No Operation

NOTES:

1. All entries assume that CKE was High during the preceding clock cycle and the current clock cycle.
2. ILLEGAL to bank in specified state; function may be legal in the bank indicated by BA, depending on the state of that bank.
3. Must satisfy bus contention, bus turn around, write recovery requirements.
4. NOP to bank precharging or in idle state. May precharge bank indicated by BA.
5. ILLEGAL if any bank is not idle.

ILLEGAL = Device operation and / or data-integrity are not guaranteed.

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FUNCTION TRUTH TABLE FOR CKE

Current State	CK _{n-1}	CK _n	/S	/RAS	/CAS	/WE	Add	Action
SELF - REFRESH*1	H	X	X	X	X	X	X	INVALID
	L	H	H	X	X	X	X	Exit Self-Refresh(Idle after tRC)
	L	H	L	H	H	H	X	Exit Self-Refresh(Idle after tRC)
	L	H	L	H	H	L	X	ILLEGAL
	L	H	L	H	L	X	X	ILLEGAL
	L	H	L	L	X	X	X	ILLEGAL
	L	L	X	X	X	X	X	NOP(Maintain Self-Refresh)
POWER DOWN	H	X	X	X	X	X	X	INVALID
	L	H	X	X	X	X	X	Exit Power Down to Idle
	L	L	X	X	X	X	X	NOP(Maintain Self-Refresh)
ALL BANKS IDLE*2	H	H	X	X	X	X	X	Refer to Function Truth Table
	H	L	L	L	L	H	X	Enter Self-Refresh
	H	L	H	X	X	X	X	Enter Power Down
	H	L	L	H	H	H	X	Enter Power Down
	H	L	L	H	H	L	X	ILLEGAL
	H	L	L	H	L	X	X	ILLEGAL
	H	L	L	L	X	X	X	ILLEGAL
	L	X	X	X	X	X	X	Refer to Current State = Power Down
ANY STATE other than listed above	H	H	X	X	X	X	X	Refer to Function Truth Table
	H	L	X	X	X	X	X	Begin CK0 Suspend at Next Cycle*3
	L	H	X	X	X	X	X	Exit CK0 Suspend at Next Cycle*3
	L	L	X	X	X	X	X	Maintain CK0 Suspend

ABBREVIATIONS:

H = High Level, L = Low Level, X = Don't Care

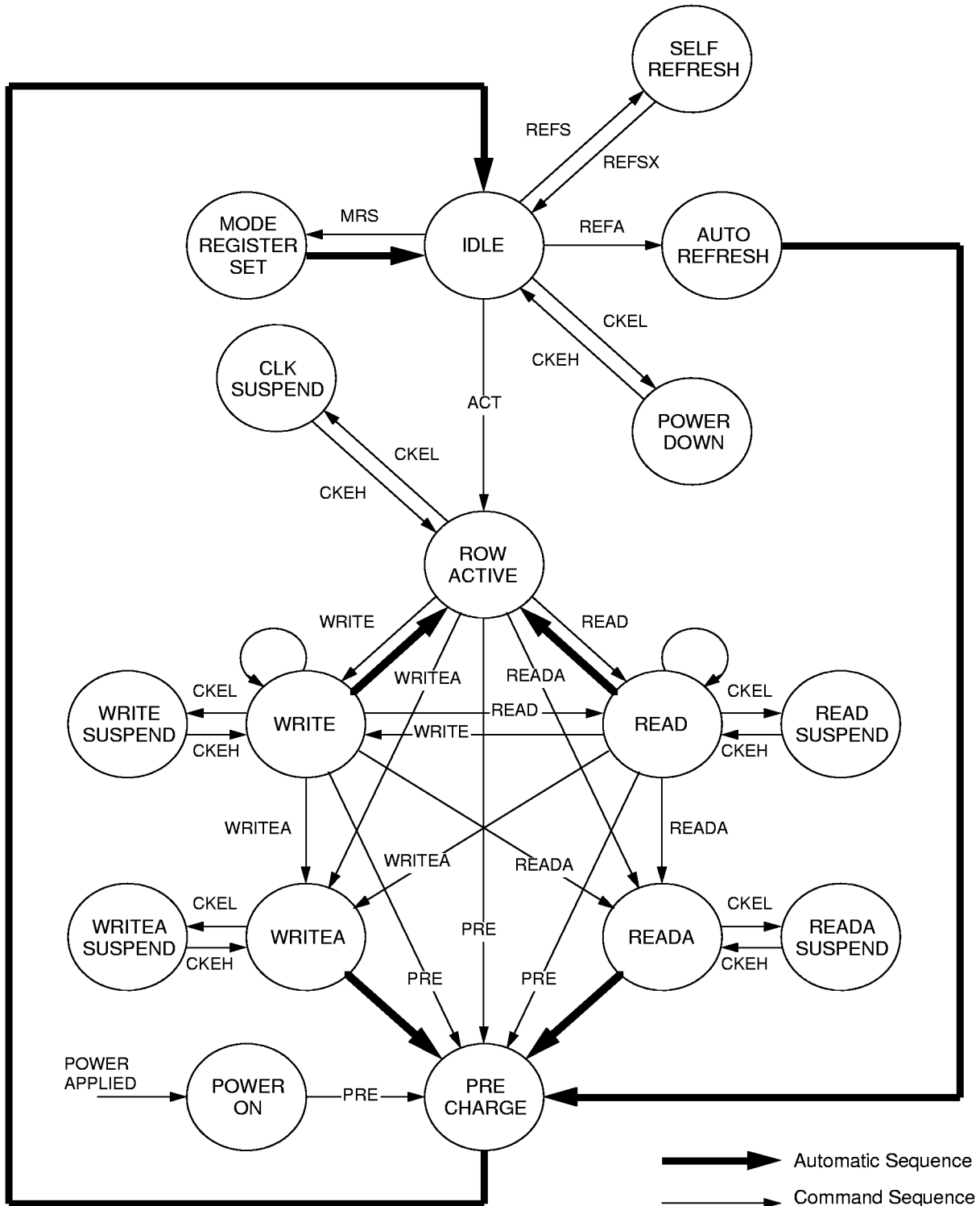
NOTES:

1. CKE Low to High transition will re-enable CK and other inputs **asynchronously**. A minimum setup time must be satisfied before any command other than EXIT.
2. Power-Down and Self-Refresh can be entered only from the All banks idle State.
3. Must be legal command.

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SIMPLIFIED STATE DIAGRAM



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POWER ON SEQUENCE

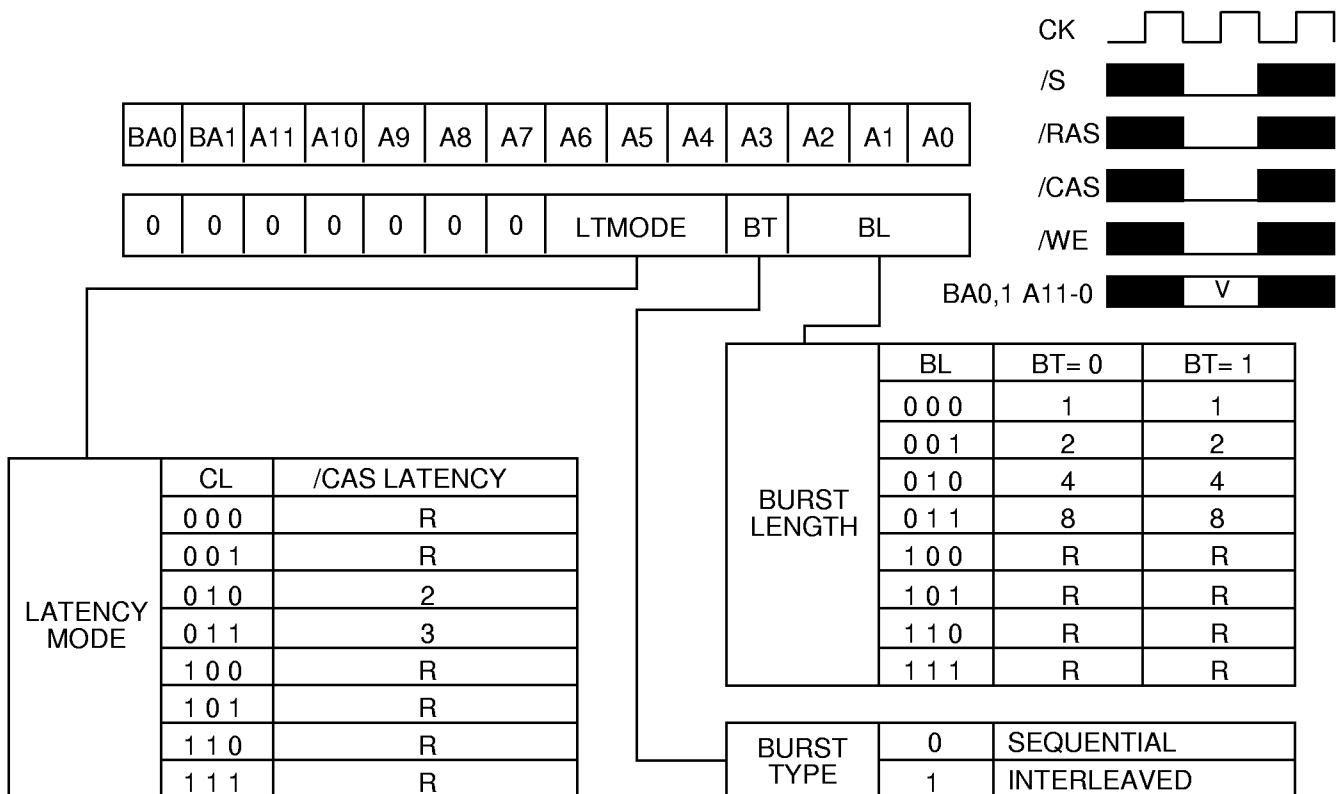
Before starting normal operation, the following power on sequence is necessary to prevent a SDRAM from damaged or malfunctioning.

1. Apply power and start clock. Attempt to maintain CKE high, DQMB0-7 high and NOP condition at the inputs.
2. Maintain stable power, stable clock, and NOP input conditions for a minimum of 500us.
3. Issue precharge commands for all banks. (PRE or PREA)
4. After all banks become idle state (after tRP), issue 8 or more auto-refresh commands.
5. Issue a mode register set command to initialize the mode register.

After these sequence, the SDRAM is idle state and ready for normal operation.

MODE REGISTER

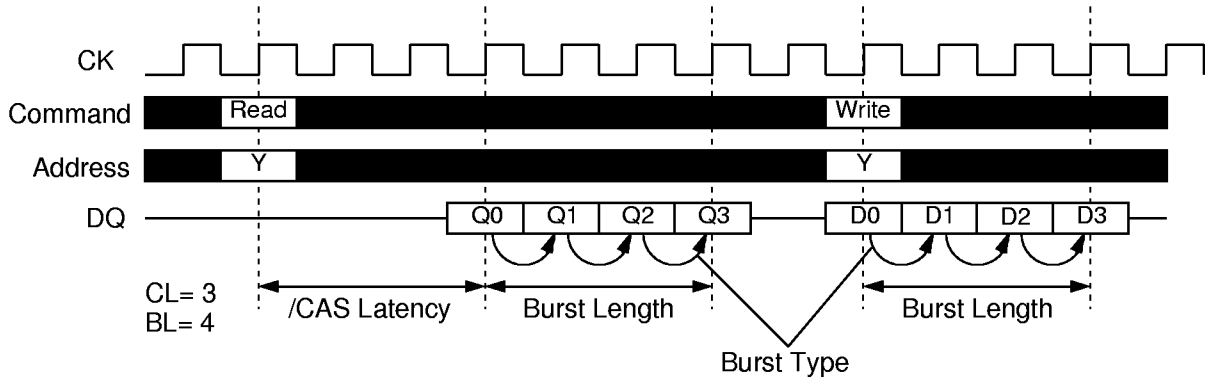
Burst Length, Burst Type and /CAS Latency can be programmed by setting the mode register(MRS). The mode register stores these data until the next MRS command, which may be issue when both banks are in idle state. After tRSC from a MRS command, the SDRAM is ready for new command.



R:Reserved for Future Use

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Initial Address			BL	Column Addressing															
A2	A1	A0		Sequential								Interleaved							
0	0	0	8	0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7
0	0	1		1	2	3	4	5	6	7	0	1	0	3	2	5	4	7	6
0	1	0		2	3	4	5	6	7	0	1	2	3	0	1	6	7	4	5
0	1	1		3	4	5	6	7	0	1	2	3	2	1	0	7	6	5	4
1	0	0		4	5	6	7	0	1	2	3	4	5	6	7	0	1	2	3
1	0	1		5	6	7	0	1	2	3	4	5	4	7	6	1	0	3	2
1	1	0		6	7	0	1	2	3	4	5	6	7	4	5	2	3	0	1
1	1	1		7	0	1	2	3	4	5	6	7	6	5	4	3	2	1	0
-	0	0	4	0	1	2	3					0	1	2	3				
-	0	1		1	2	3	0					1	0	3	2				
-	1	0		2	3	0	1					2	3	0	1				
-	1	1		3	0	1	2					3	2	1	0				
-	-	0	2	0	1							0	1						
-	-	1		1	0							1	0						

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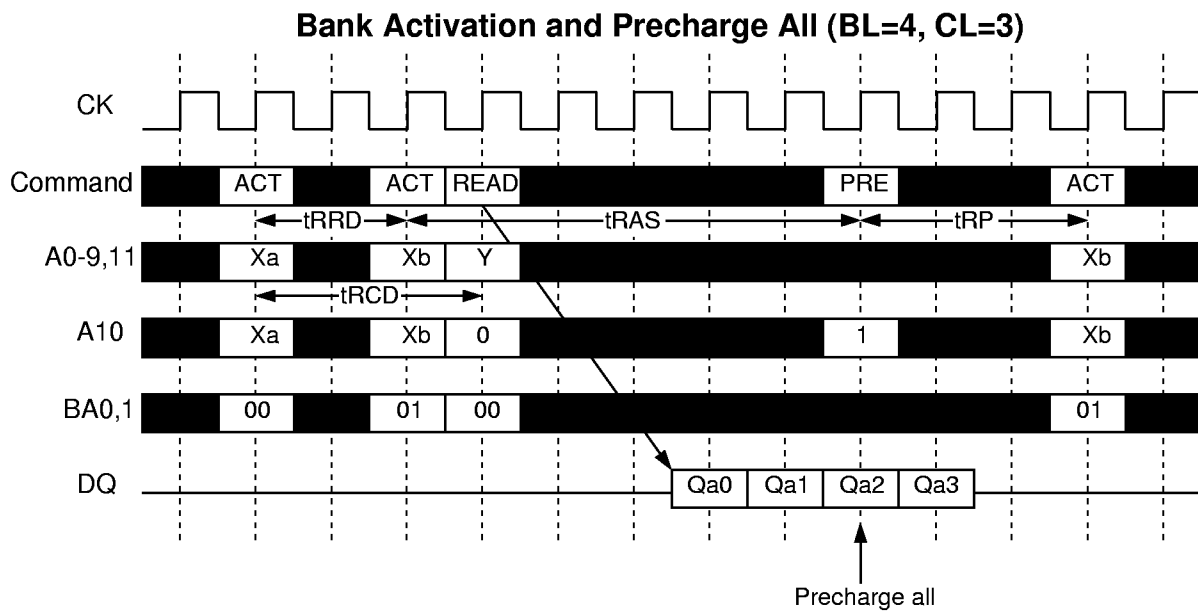
OPERATION DESCRIPTION

BANK ACTIVATE

The SDRAM has four independent banks. Each bank is activated by the ACT command with the bank address(BA0,1). A row is indicated by the row address A11-0. The minimum activation interval between one bank and the other bank is tRRD.

PRECHARGE

The PRE command deactivates indicated by BA0,1. When multiple banks are active, the precharge all command(PREA,PRE + A10=H) is available to deactivate them at the same time. After tRP from the precharge, an ACT command can be issued.



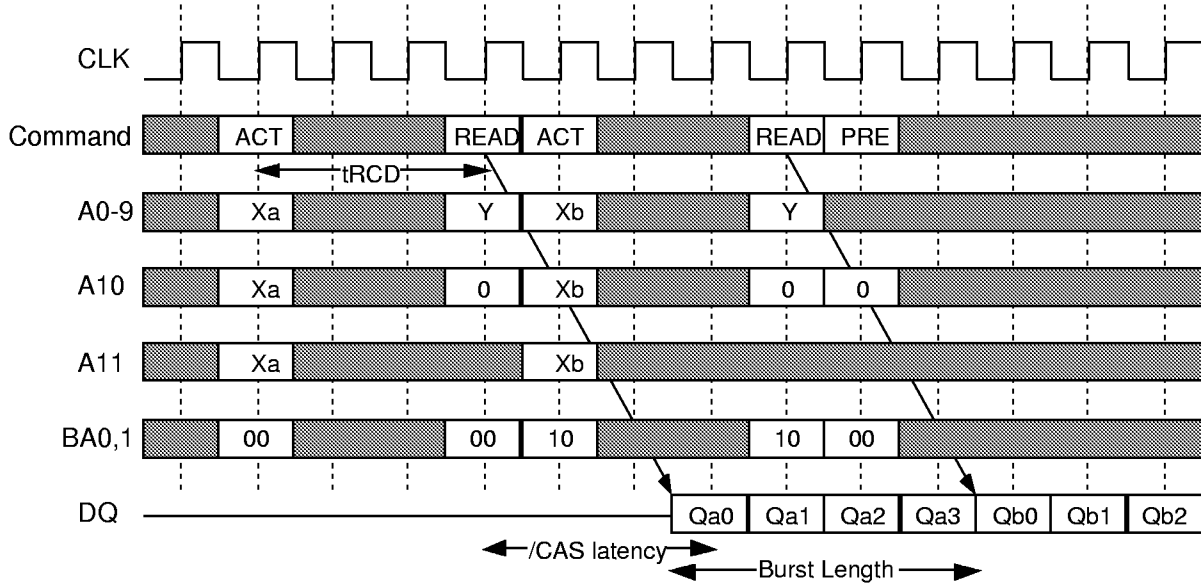
READ

After tRCD from the bank activation, a READ command can be issued. 1st output data is available after the /CAS Latency from the READ, followed by (BL-1) consecutive data when the Burst Length is BL. The start address is specified by A8-0, and the address sequence of burst data is defined by the Burst Type. A READ command may be applied to any active bank, so the row precharge time(tRP) can be hidden behind continuous output data(in case of BL=8) by interleaving the multiple banks. When A10 is high at a READ command, the auto-precharge(READA) is performed. Any command (READ, WRITE, PRE, ACT) to the same bank is inhibited till the internal precharge is complete. The internal precharge starts at BL after READA. The next ACT command can be issued after (BL + tRP) from the previous READA.

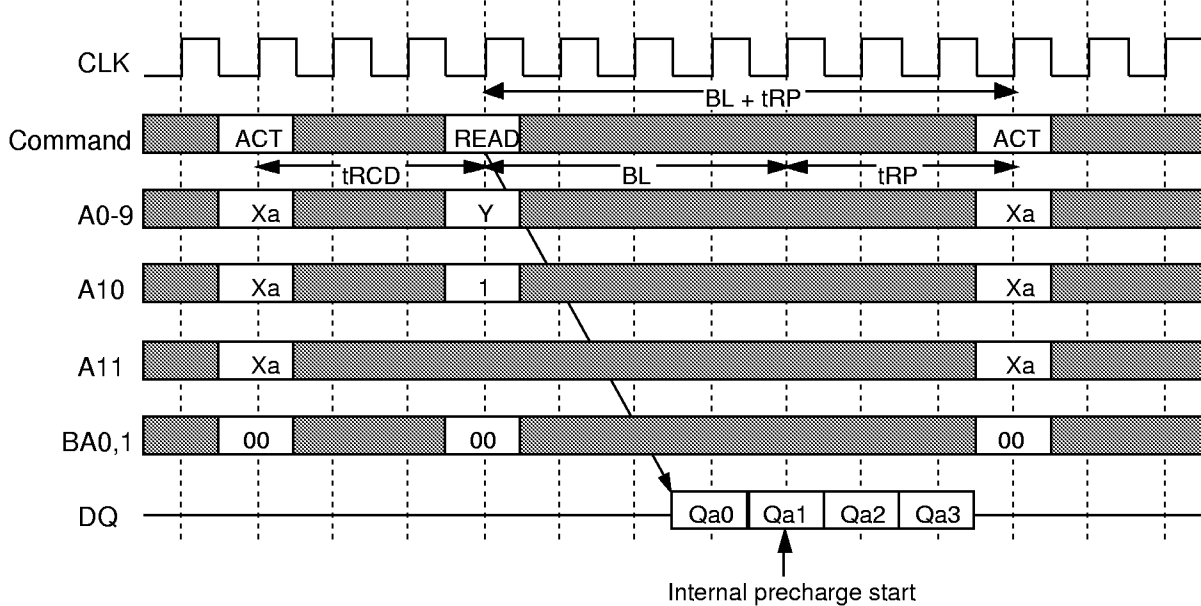
MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

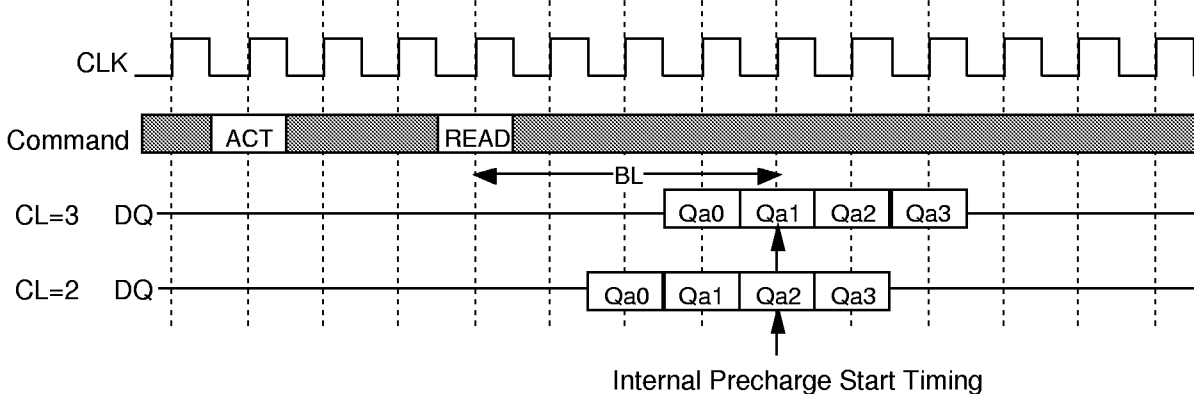
Multi Bank Interleaving READ (BL=4, CL=3)



READ with Auto-Precharge (BL=4, CL=3)



READ Auto-Precharge Timing (BL=4)



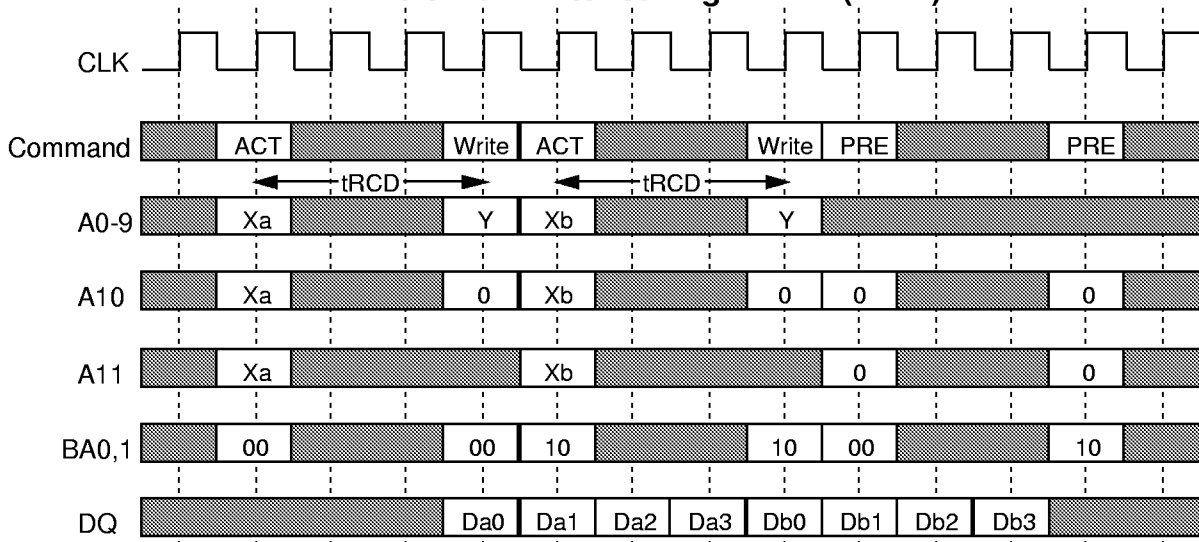
MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

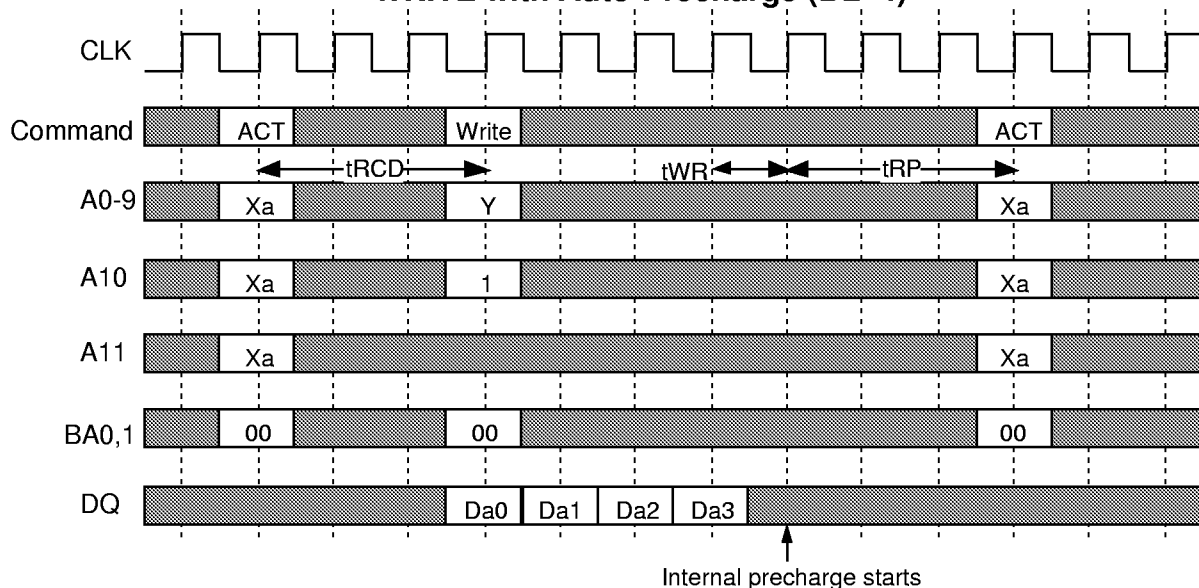
WRITE

After tRCD from the bank activation, a WRITE command can be issued. 1st input data is set at the same cycle as the WRITE. Following (BL -1) data are written into the RAM, when the Burst Length is BL. The start address is specified by A8-0 (x 8), A9-0 (x 4) and the address sequence of burst data is defined by the Burst Type. A WRITE command may be applied to any active bank, so the row precharge time (tRP) can be hidden behind continuous input data by interleaving the multiple banks. From the last input data to the PRE command, the write recovery time (tWR) is required. When A10 is high at a WRITE command, the auto-precharge (WRITEEA) is performed. Any command (READ, WRITE, PRE, ACT) to the same bank is inhibited till the internal precharge is complete. The internal precharge begins at tWR after the last input data cycle. The next ACT command can be issued after tRP from the internal precharge timing.

Multi Bank Interleaving WRITE (BL=4)



WRITE with Auto-Precharge (BL=4)



MH8S64AKD -8,-10,-8L,-10L

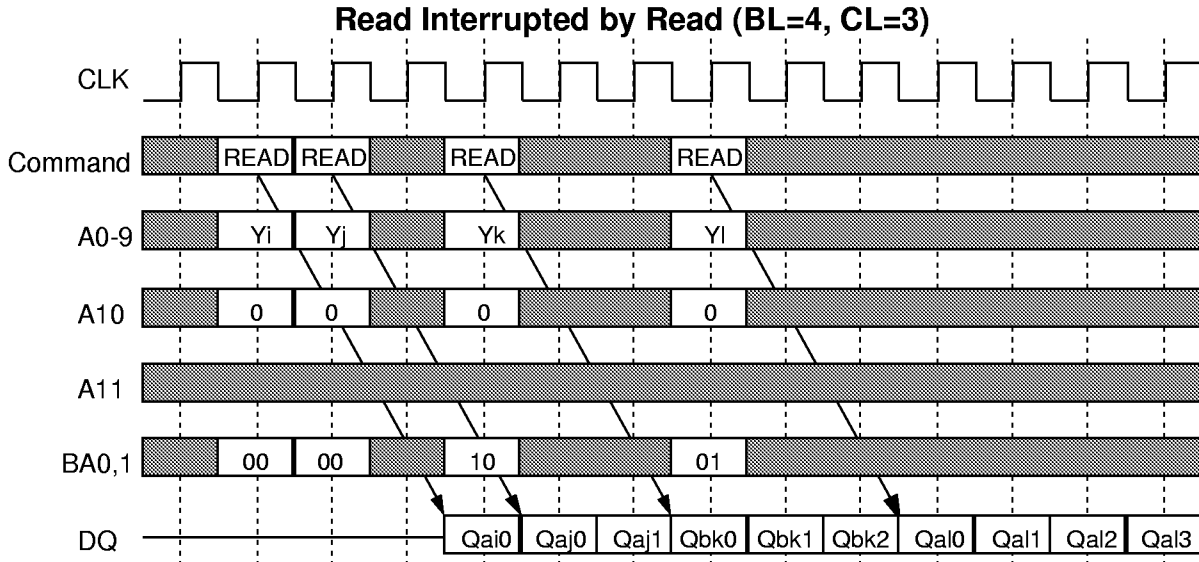
536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

BURST INTERRUPTION

[Read Interrupted by Read]

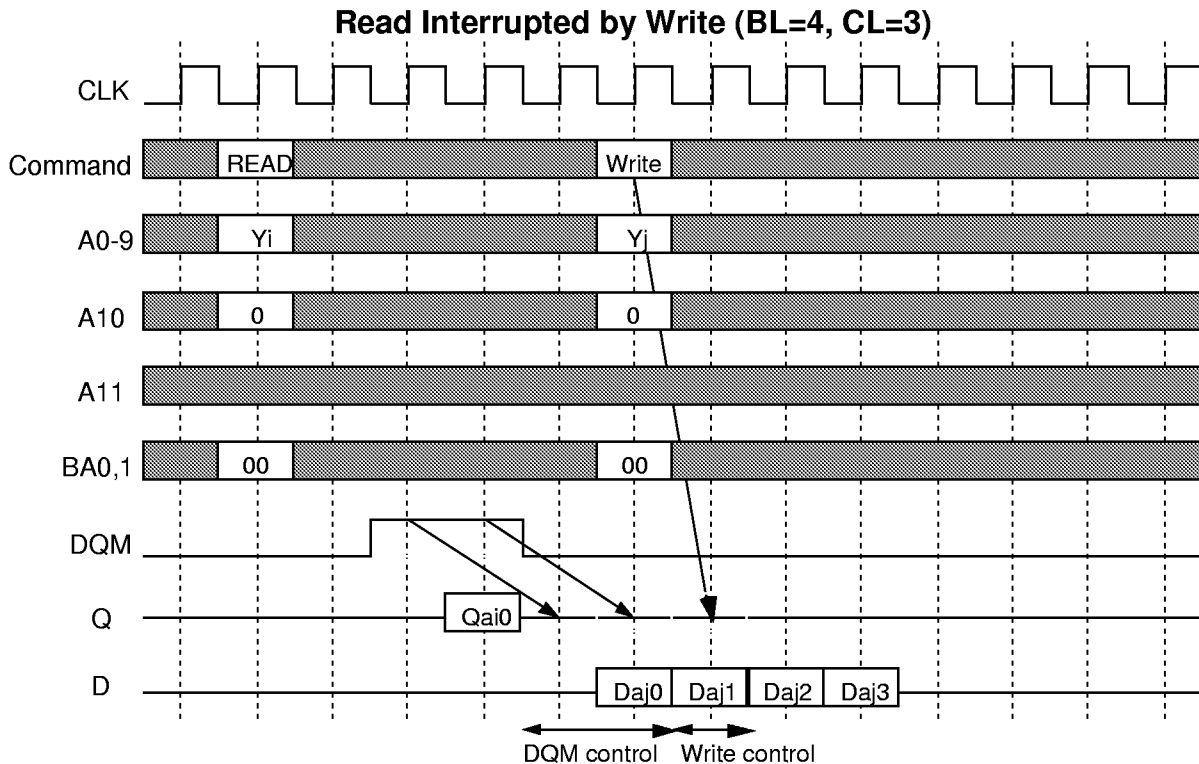
Burst read operation can be interrupted by new read of any bank. Random column access is allowed.

READ to READ interval is minimum 1 CLK.



[Read Interrupted by Write]

Burst read operation can be interrupted by write of any bank. Random column access is allowed. In this case, the DQ should be controlled adequately by using the DQM to prevent the bus contention. The output is disabled automatically 1 cycle after WRITE assertion.

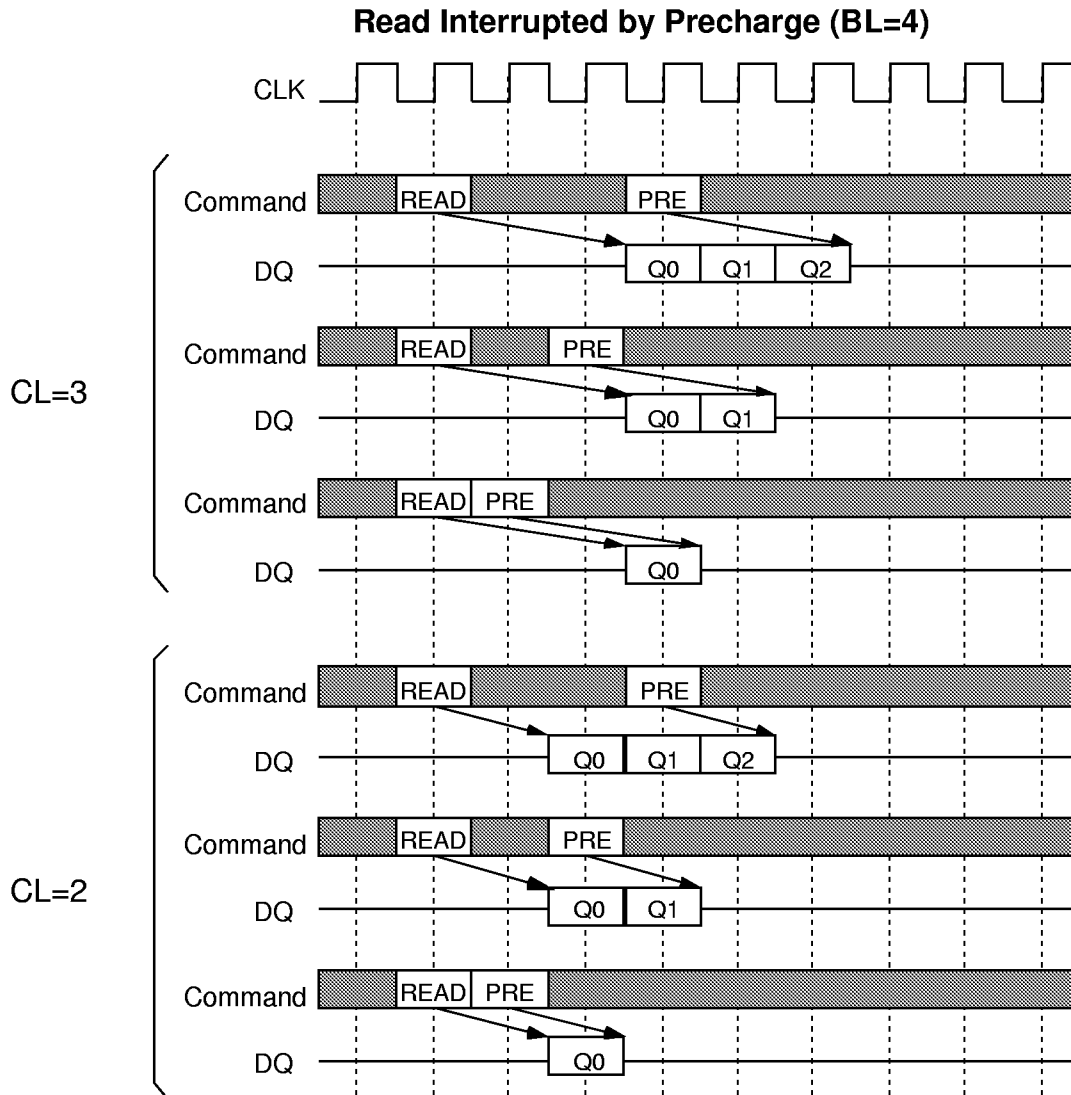


MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

[Read Interrupted by Precharge]

Burst read operation can be interrupted by precharge of *the same bank* . READ to PRE interval is minimum 1 CLK. A PRE command to output disable latency is equivalent to the /CAS Latency. As a result, READ to PRE interval determines valid data length to be output. The figure below shows examples of BL=4.



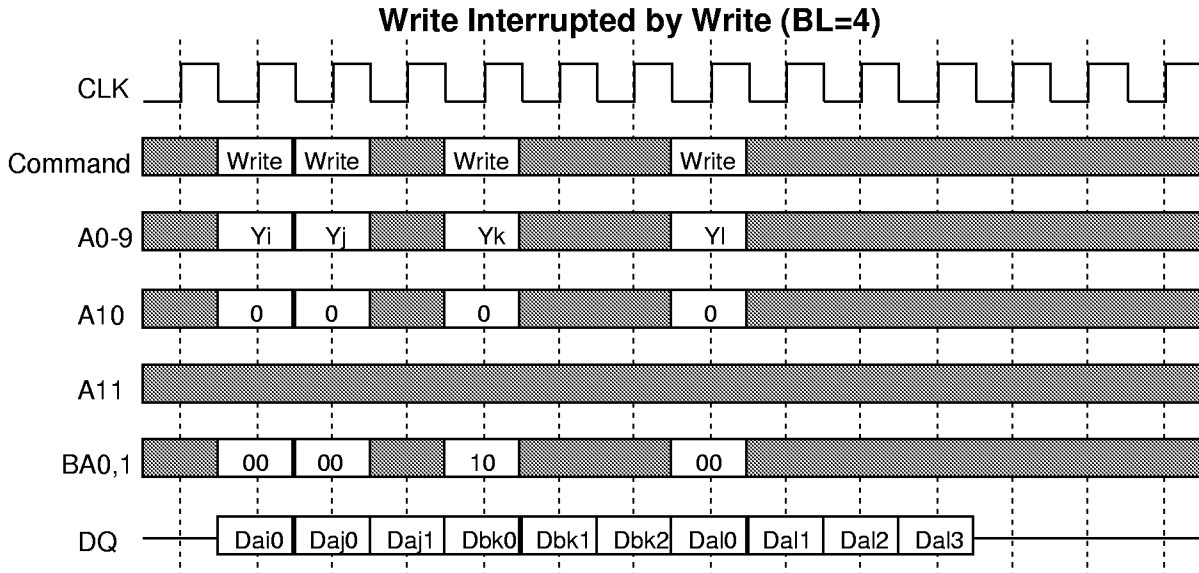
MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

[Write Interrupted by Write]

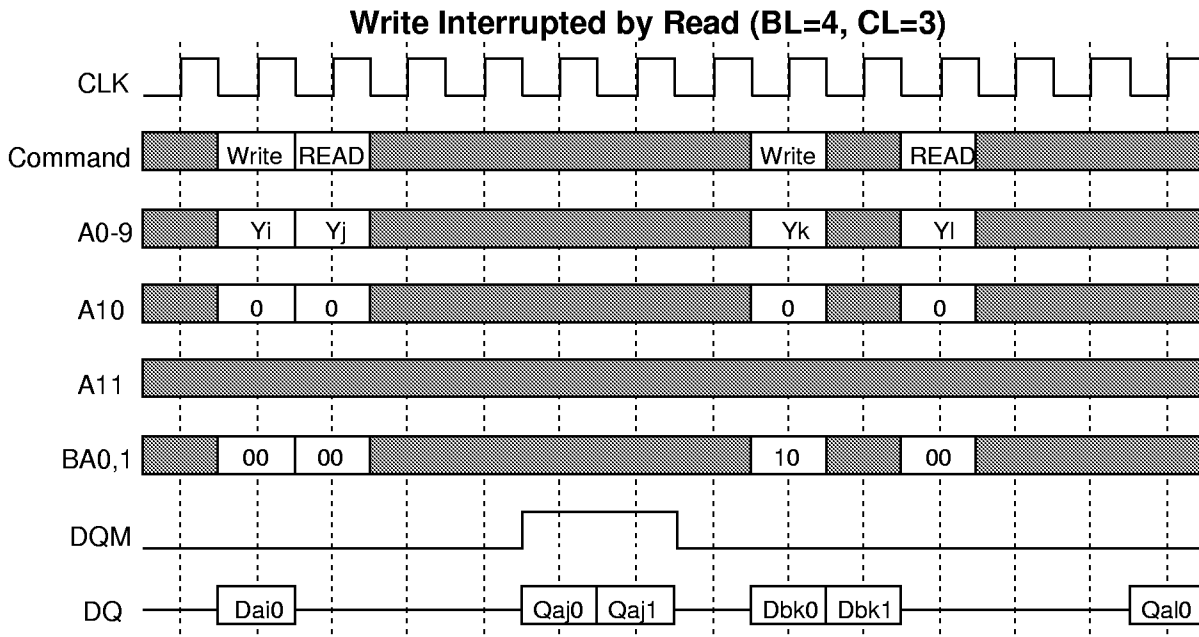
Burst write operation can be interrupted by new write of any bank. Random column access is allowed.

WRITE to WRITE interval is minimum 1 CLK.



[Write Interrupted by Read]

Burst write operation can be interrupted by read of the same or the other bank. Random column access is allowed. WRITE to READ interval is minimum 1 CLK. The input data on DQ at the interrupting READ cycle is "don't care".



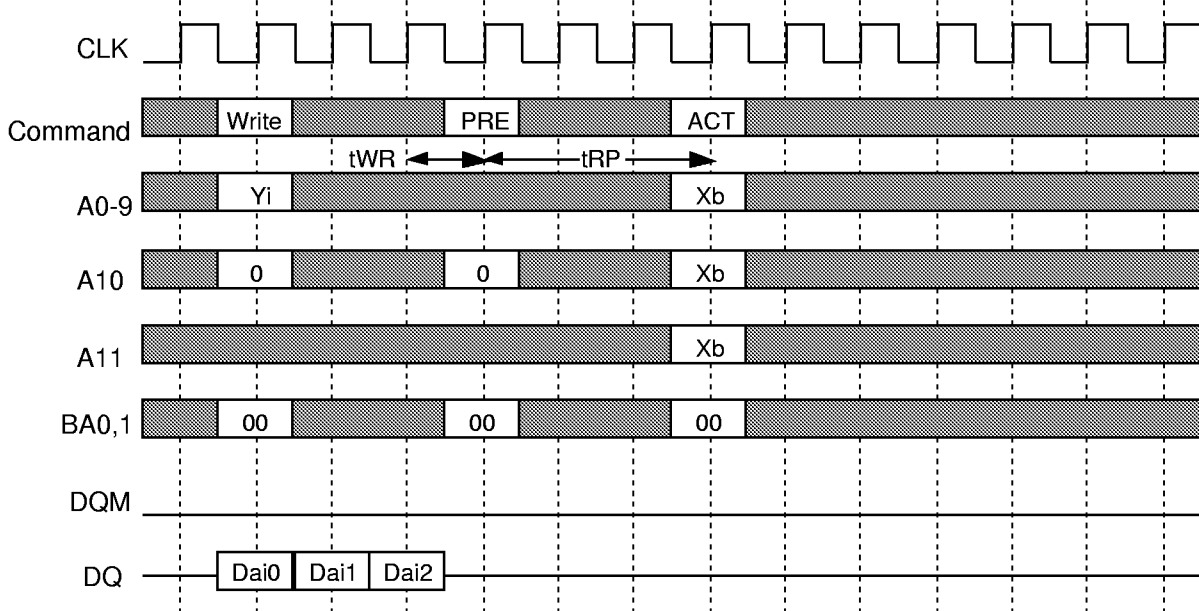
MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

[Write Interrupted by Precharge]

Burst write operation can be interrupted by precharge of *the same bank* . Random column access is allowed. Write recovery time (t_{WR}) is required from the last data to PRE command.

Write Interrupted by Precharge (BL=4)

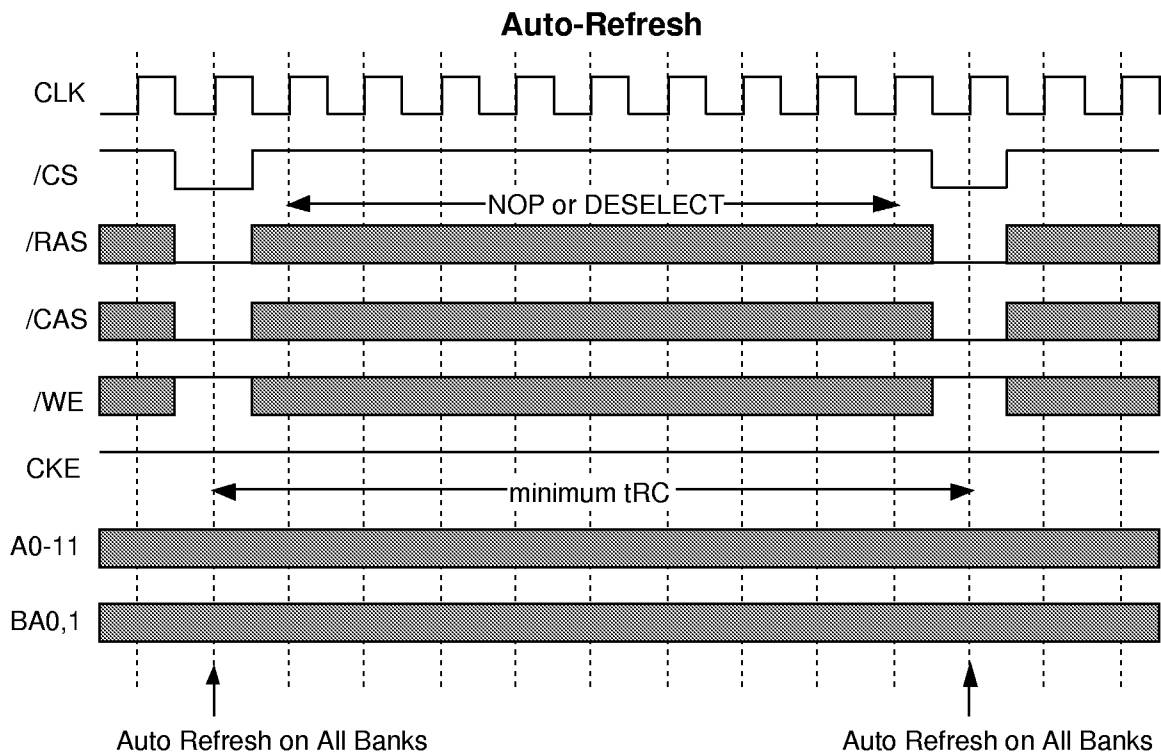


MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

AUTO REFRESH

Single cycle of auto-refresh is initiated with a REFA (/CS= /RAS= /CAS= L, /WE= /CKE= H) command. The refresh address is generated internally. 4096 REFA cycles within 64ms refresh 64Mbit memory cells. The auto-refresh is performed on 4 banks concurrently. Before performing an auto-refresh, all banks must be in the idle state. Auto-refresh to auto-refresh interval is minimum t_{RC}. Any command must not be supplied to the device before t_{RC} from the REFA command.



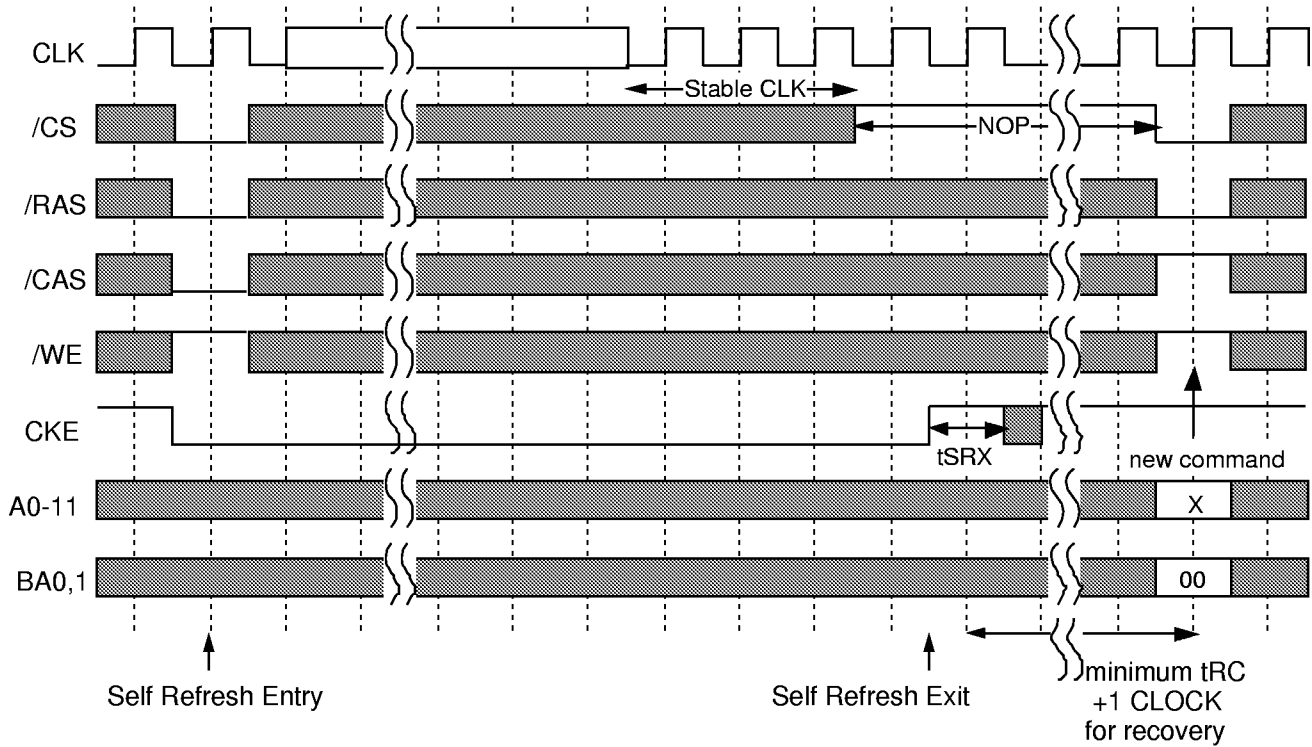
MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

SELF REFRESH

Self-refresh mode is entered by issuing a REFS command (/CS= /RAS= /CAS= L, /WE= H, CKE= L). Once the self-refresh is initiated, it is maintained as long as CKE is kept low. During the self-refresh mode, CKE is asynchronous and the only enabled input, all other inputs including CLK are disabled and ignored, so that power consumption due to synchronous inputs is saved. To exit the self-refresh, supplying stable CLK inputs, asserting DESEL or NOP command and then asserting CKE (REFSX) for longer than tSRX. After tRC from REFSX all banks are in the idle state and a new command can be issued, but DESEL or NOP commands must be asserted till then.

Self-Refresh

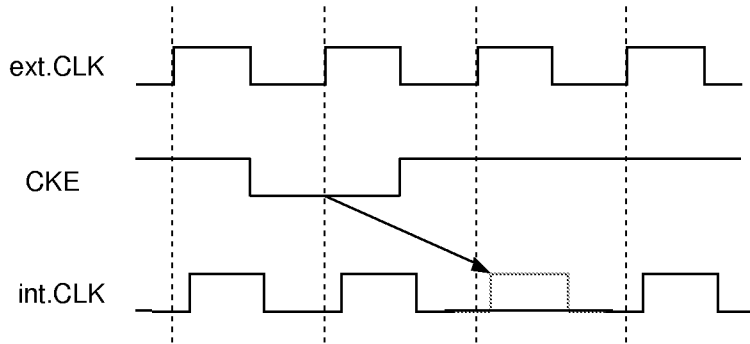


MH8S64AKD -8,-10,-8L,-10L

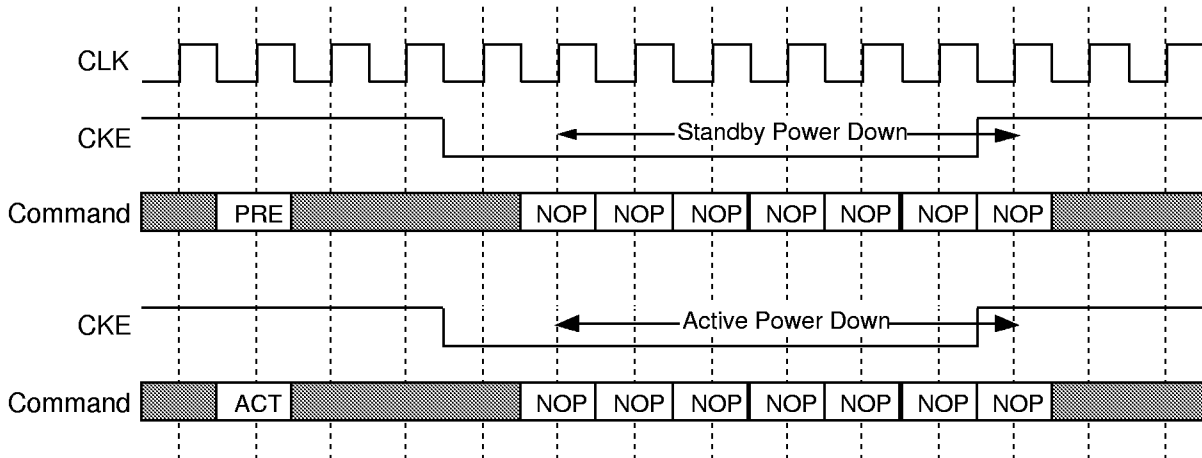
536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

CLK SUSPEND

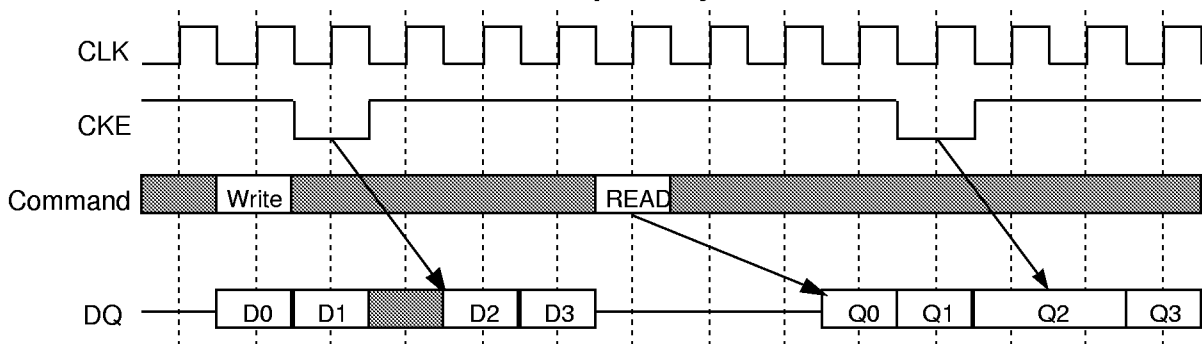
CKE controls the internal CLK at the following cycle. Figure below shows how CKE works. By negating CKE, the next internal CLK is suspended. The purpose of CLK suspend is power down, output suspend or input suspend. CKE is a synchronous input except during the self-refresh mode. CLK suspend can be performed either when the banks are active or idle. A command at the suspended cycle is ignored.



Power Down by CKE



DQ Suspend by CKE



MH8S64AKD -8,-10,-8L,-10L

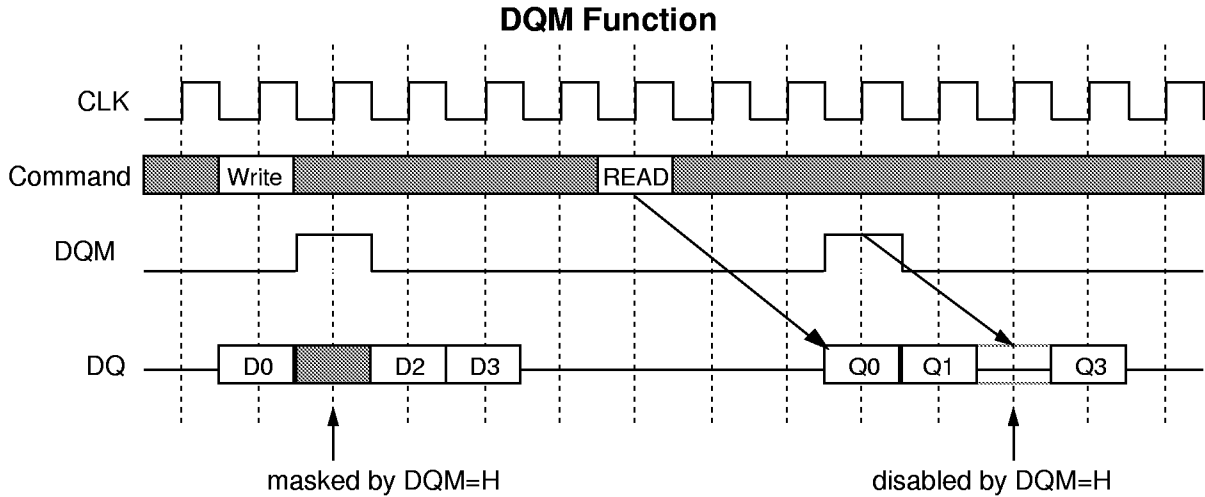
536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

DQM CONTROL

DQM is a dual function signal defined as the data mask for writes and the output disable for reads.

During writes, DQM masks input data word by word. DQM to write mask latency is 0.

During reads, DQM forces output to Hi-Z word by word. DQM to output Hi-Z latency is 2.



MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Condition	Ratings	Unit
Vdd	Supply Voltage	with respect to Vss	-0.5 ~ 4.6	V
VI	Input Voltage	with respect to Vss	-0.5 ~ Vdd+0.5	V
VO	Output Voltage	with respect to Vss	-0.5 ~ Vdd+0.5	V
IO	Output Current		50	mA
Pd	Power Dissipation	Ta=25°C	8	W
Topr	Operating Temperature		0 ~ 70	°C
Tstg	Storage Temperature		-40 ~ 100	°C

RECOMMENDED OPERATING CONDITION

(Ta=0 ~ 70°C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
Vdd	Supply Voltage	3.0	3.3	3.6	V
Vss	Supply Voltage	0	0	0	V
VIH	High-Level Input Voltage all inputs	2.0		Vdd+0.3	V
VIL	Low-Level Input Voltage all inputs	-0.3		0.8	V

CAPACITANCE

(Ta=0 ~ 70°C, Vdd = 3.3 ± 0.3V, Vss = 0V, unless otherwise noted)

Symbol	Parameter	Test Condition	Limits(max.)	Unit
CI(A)	Input Capacitance, address pin	VI = Vss f=1MHz Vi=25mVrms	55	pF
CI(C)	Input Capacitance, control pin		55	pF
CI(K)	Input Capacitance, CK pin		35	pF
CI/O	Input Capacitance, I/O pin		22	pF

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

AVERAGE SUPPLY CURRENT from Vdd

(Ta=0 ~70°C, Vdd = 3.3 ± 0.3V, Vss = 0V, unless otherwise noted)

Symbol	Parameter	Test Condition	Limits(max)		Unit	
			-8,-8L	-10,-10L		
lcc1s	operating current, single bank (discrete)	tRC=min.tCLK=min, BL=1, CL=3	880	680	mA	
lcc1d	operating current, dual bank (discrete)	tRC=min.tCLK=min, BL=1, CL=3	920	920	mA	
lcc2h	standby current, CKE=H	both banks idle, tCLK=min, CKE=H	176	176	mA	
lcc2l	standby current, CKE=L	both banks idle, tCLK=min, CKE=L	16	16	mA	
lcc3	active standby current	both banks active, tCLK=min, CKE=H	360	360	mA	
lcc4	burst current	tCLK=min, BL=4, CL=3, both banks active(discerte)	920	920	mA	
lcc5	auto-refresh current	tRC=min, tCLK=min	1200	920	mA	
lcc6	self-refresh current	CKE <0.2V	-8,-10	8	8	mA
			-8L,-10L	4	4	mA

AC OPERATING CONDITIONS AND CHARACTERISTICS

(Ta=0 ~ 70°C, Vdd = 3.3 ± 0.3V, Vss = 0V, unless otherwise noted)

Symbol	Parameter	Test Condition	Limits		Unit
			Min.	Max.	
VOH(DC)	High-Level Output Voltage(DC)	IOH=-2mA	2.4		V
VOL(DC)	Low-Level Output Voltage(DC)	IOL=2mA		0.4	V
IOZ	Off-stare Output Current	Q floating VO=0 ~ Vdd	-10	10	uA
li	Input Current	VIH=0 ~ Vdd+0.3V	-80	80	uA

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

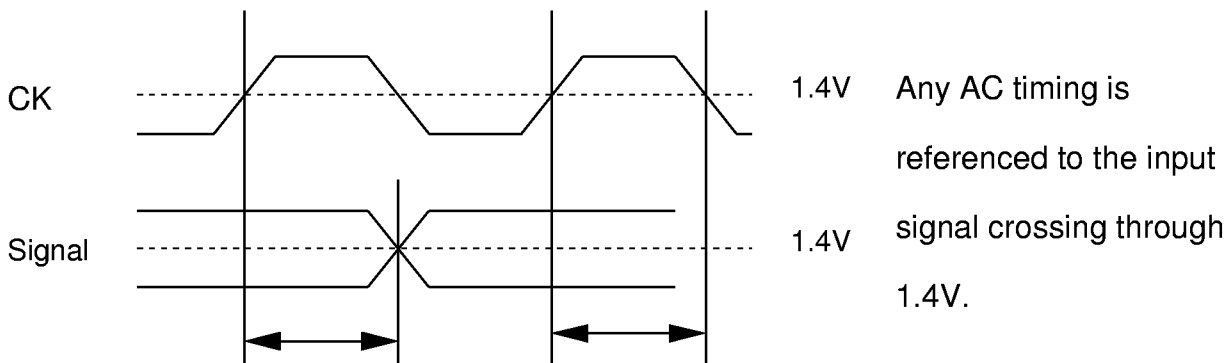
AC TIMING REQUIREMENTS (SDRAM Component)

($T_a=0 \sim 70^\circ\text{C}$, $V_{dd} = 3.3 \pm 0.3\text{V}$, $V_{ss} = 0\text{V}$, unless otherwise noted)

Input Pulse Levels: 0.8V to 2.0V

Input Timing Measurement Level: 1.4V

Symbol	Parameter	Limits				Unit
		-8,-8L		-10,-10L		
		Min.	Max.	Min.	Max.	
tCLK	CK cycle time	CL=2	—		15	ns
		CL=3	10		10	ns
tCH	CK High pulse width	3		4		ns
tCL	CK Low pulse width	3		4		ns
tT	Transition time of CK	1	10	1	10	ns
tIS	Input Setup time(all inputs)	2		3		ns
tIH	Input Hold time(all inputs)	1		1		ns
tRC	Row cycle time	70		90		ns
tRCD	Row to Column Delay	20		30		ns
tRAS	Row Active time	50	20000	60	20000	ns
tRP	Row Precharge time	20		30		ns
tWR	Write Recovery time	10		10		ns
tRRD	Act to Act Deley time	20		20		ns
tCDD	Col. to Col. Delay time	10		10		ns
tRSC	Mode Register Set Cycle time	20		20		ns
tSRX	Self Refresh Exit time	10		10		ns
tREF	Refresh Interval time		64		64	ms



MH8S64AKD -8,-10,-8L,-10L

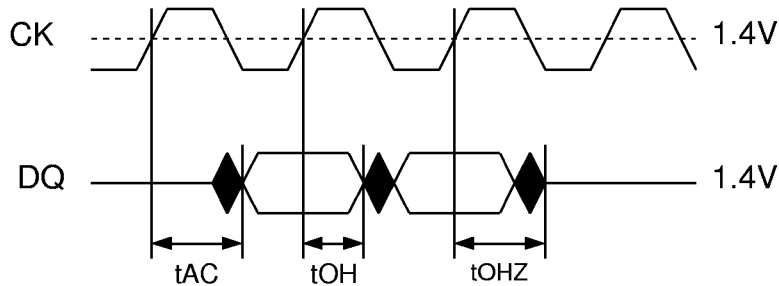
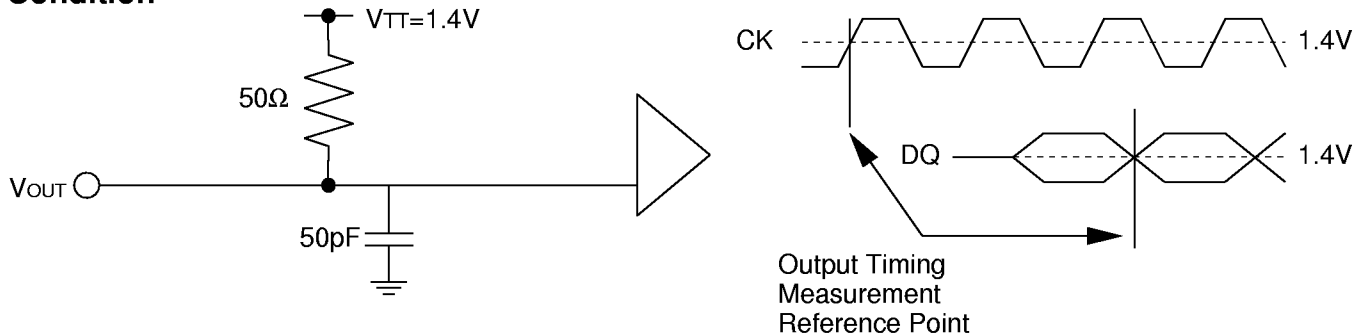
536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

SWITCHING CHARACTERISTICS (SDRAM Component)

($T_a=0 \sim 70^\circ\text{C}$, $V_{dd} = 3.3 \pm 0.165\text{V}$, $V_{ss} = 0\text{V}$, unless otherwise noted)

Symbol	Parameter	Limits				Unit
		-8,-8L		-10,-10L		
		Min.	Max.	Min.	Max.	
tAC	Access time from CK	CL=2	-		8	ns
		CL=3		6		8
tOH	Output Hold time from CK	3		3		ns
tOLZ	Delay time, output low impedance from CK	0		0		ns
tOHZ	Delay time, output high impedance from CK	3	6	3	8	ns

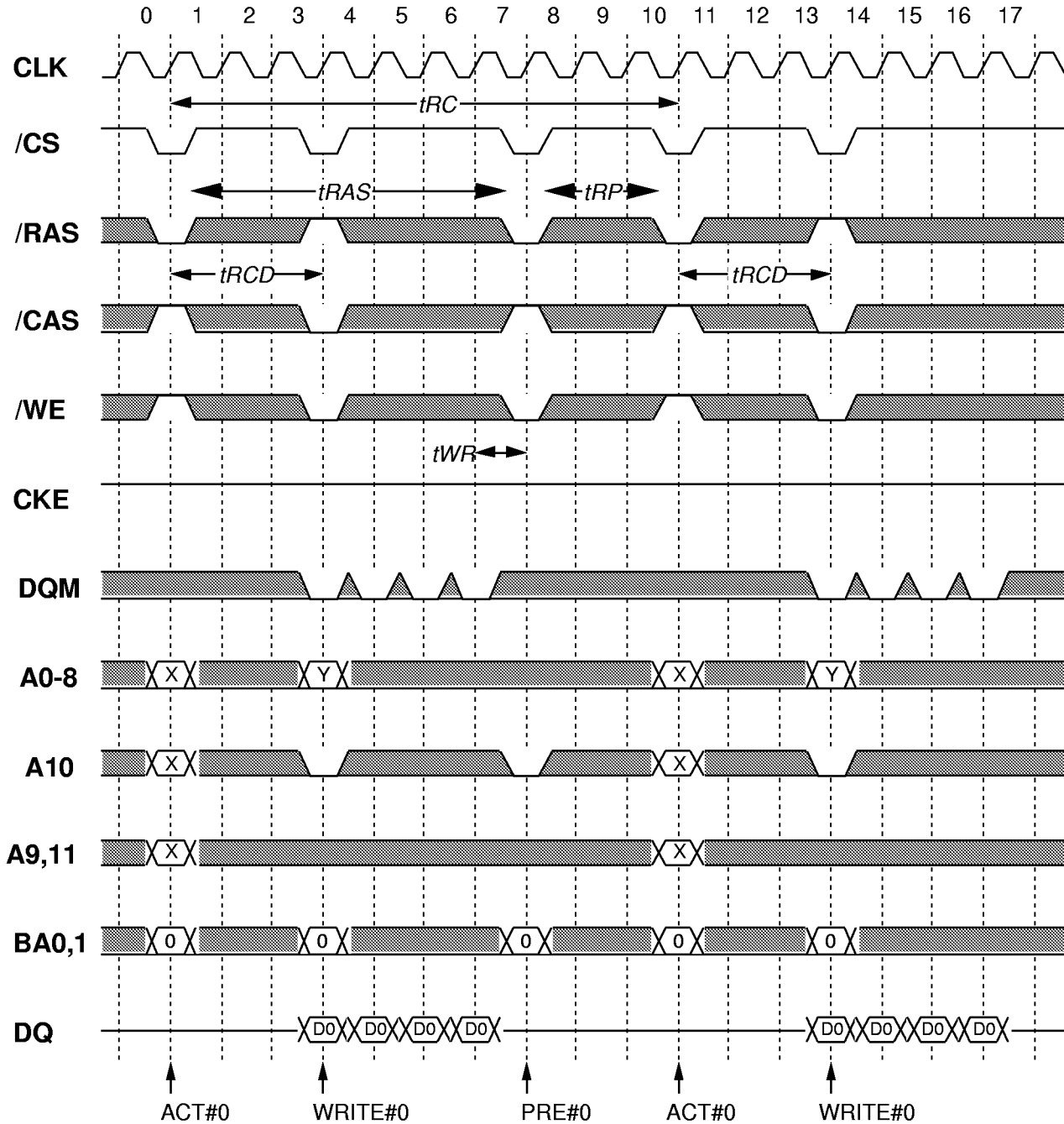
Output Load Condition



MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Write (single bank) @BL=4

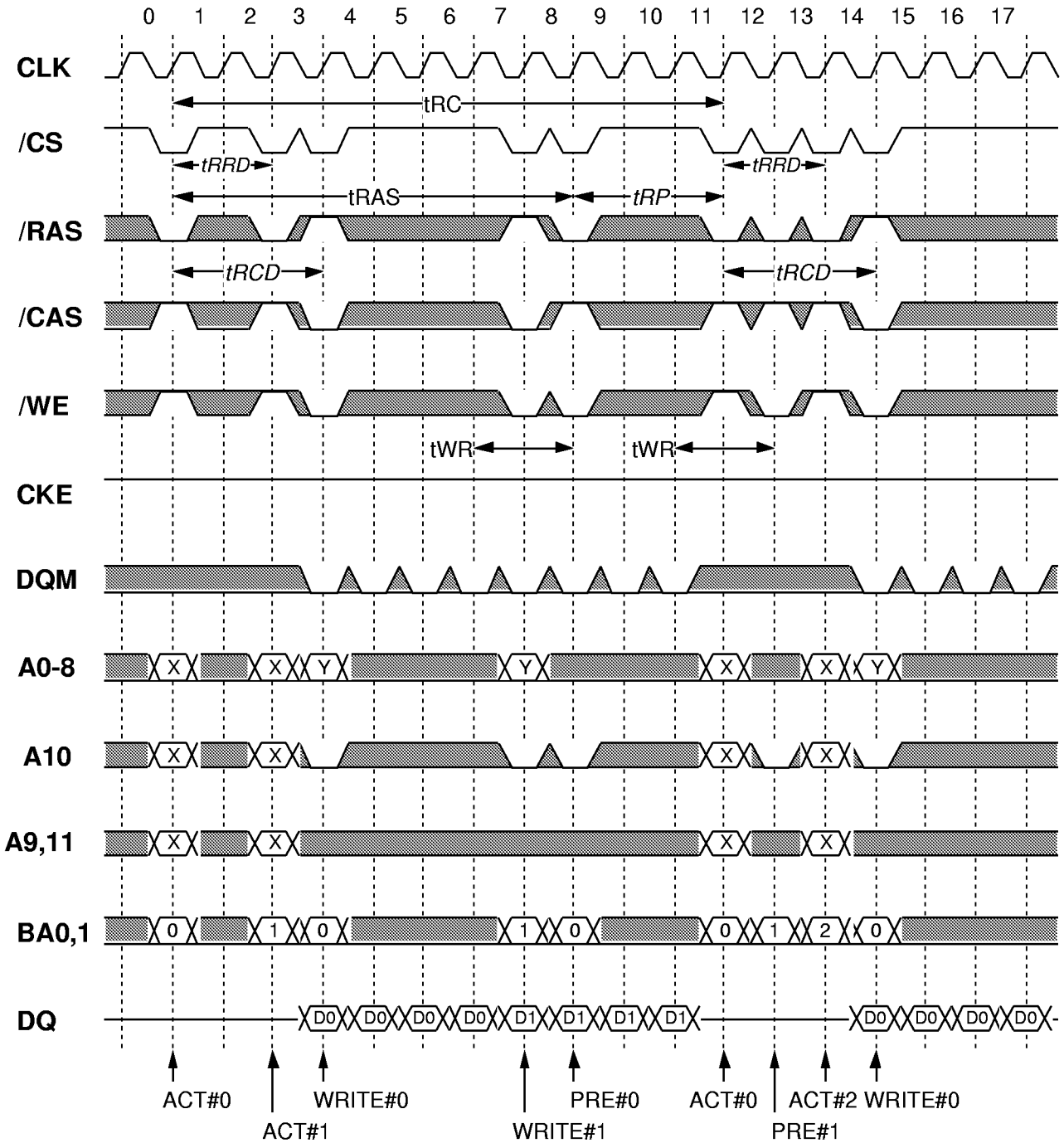


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Write (multi bank) @BL=4

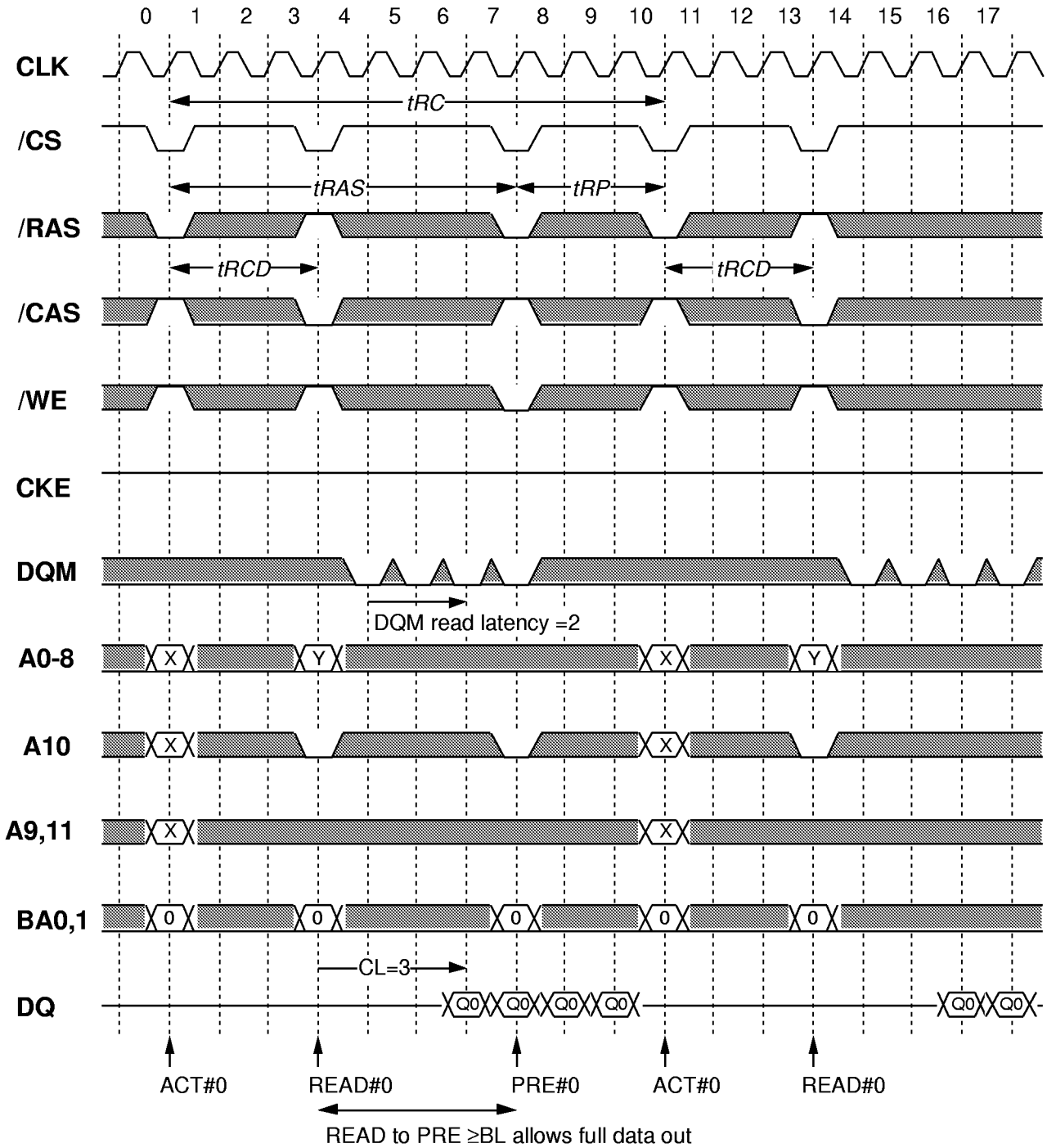


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Read (single bank) @BL=4 CL=3

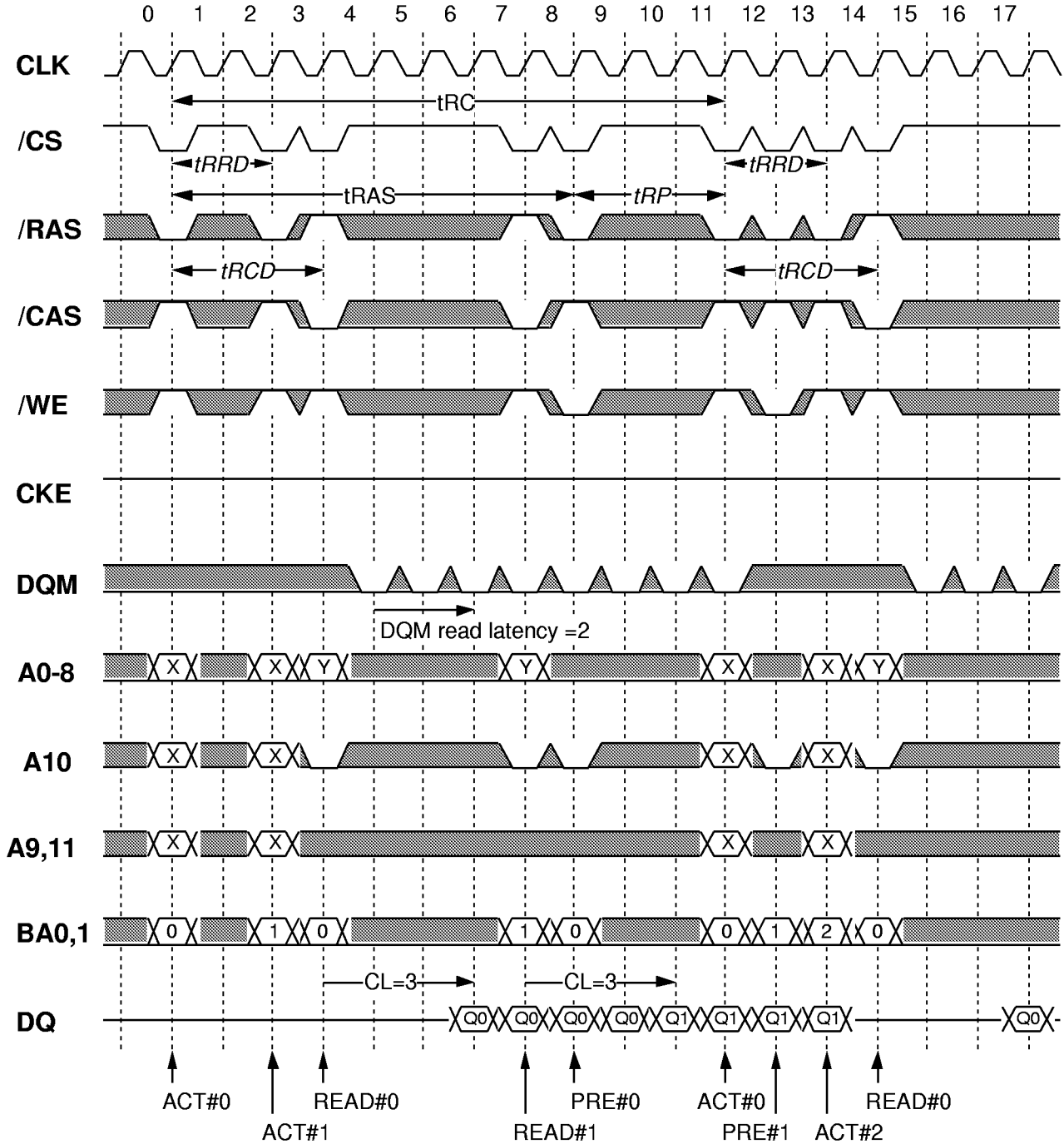


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Read (multiple bank) @BL=4 CL=3

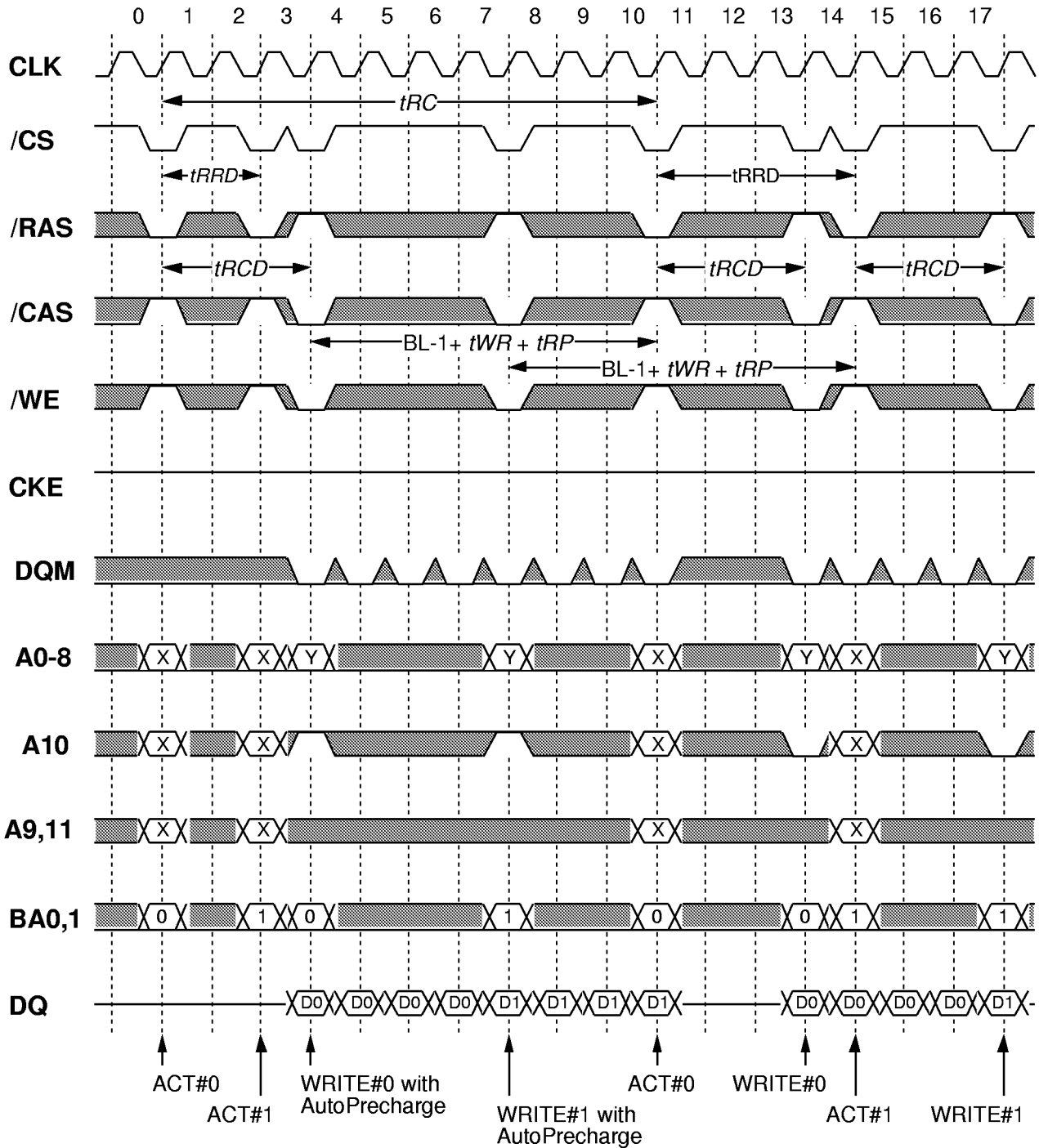


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Write (multi bank) with Auto-Precharge @BL=4

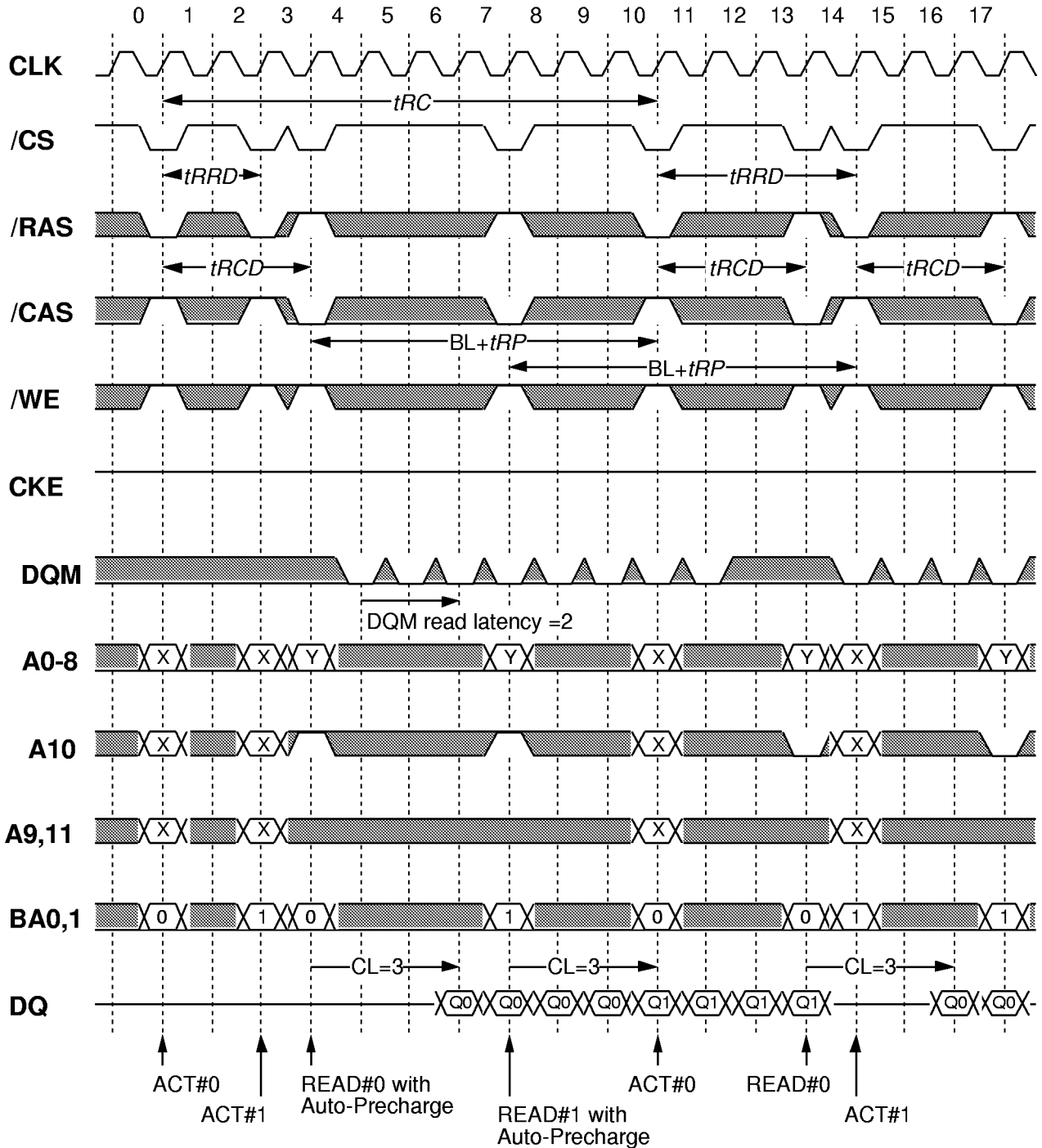


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Burst Read (multiple bank) with Auto-Precharge @BL=4 CL=3

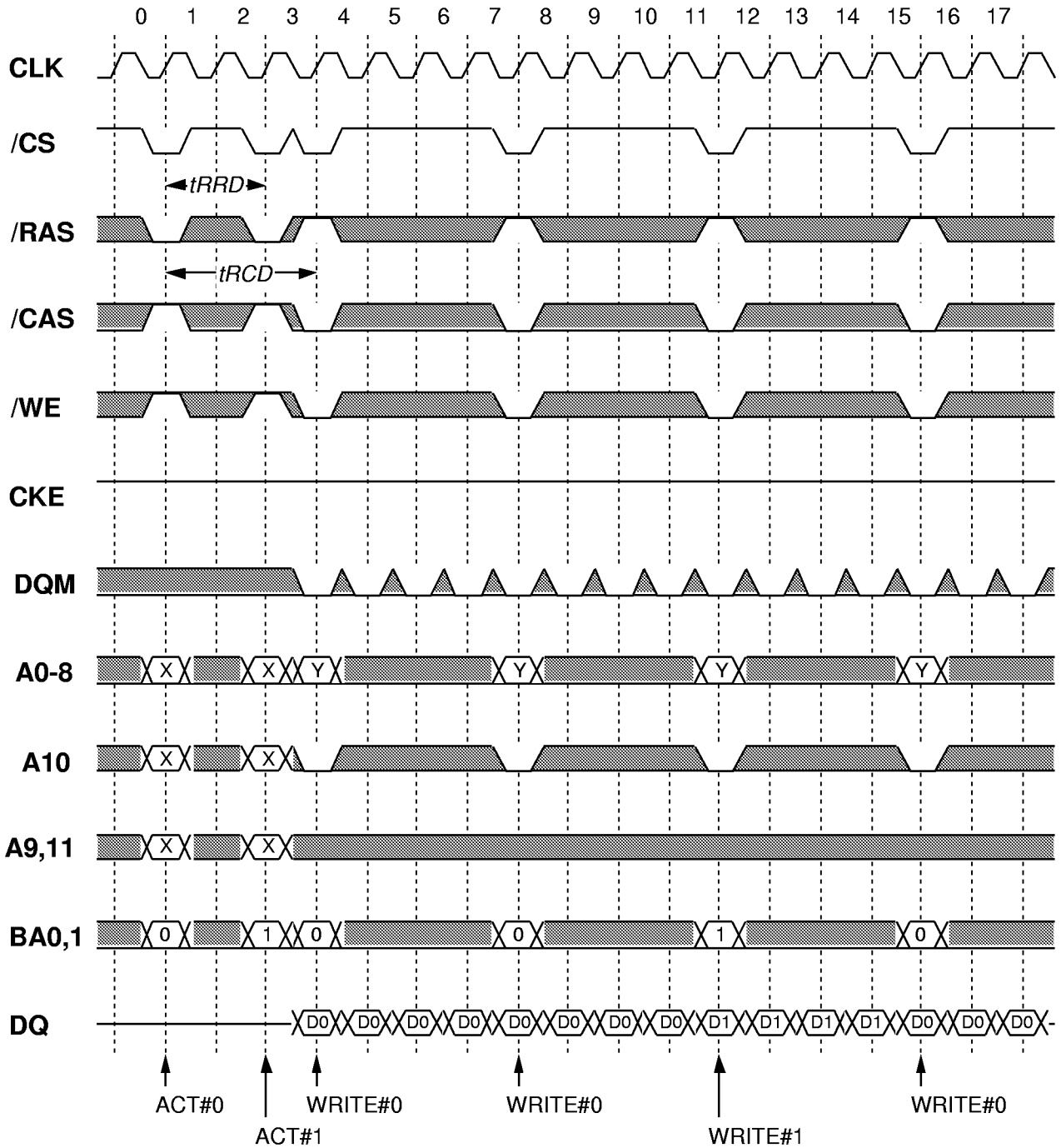


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Page Mode Burst Write (multi bank) @BL=4

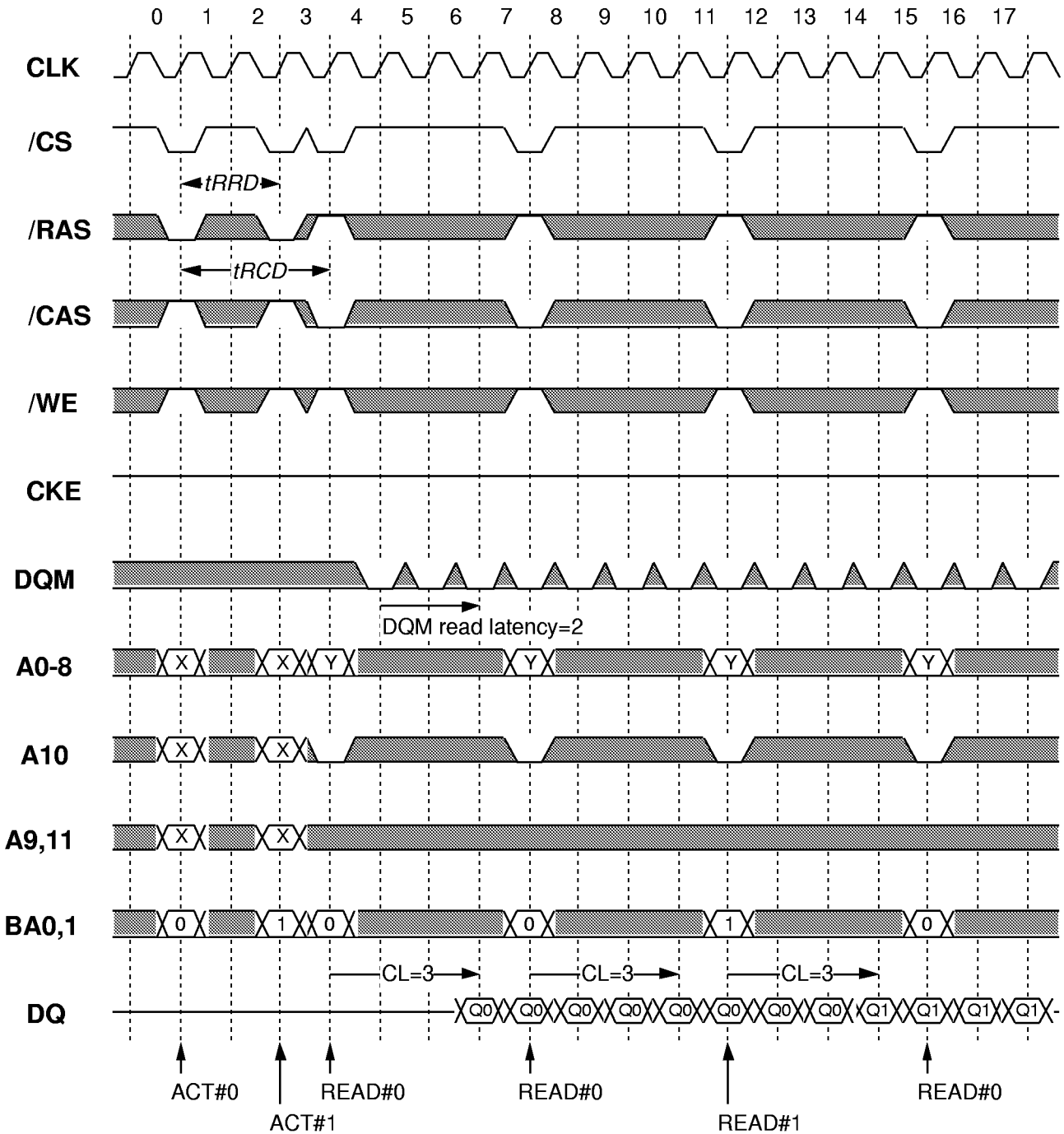


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Page Mode Burst Read (multi bank) @BL=4 CL=3

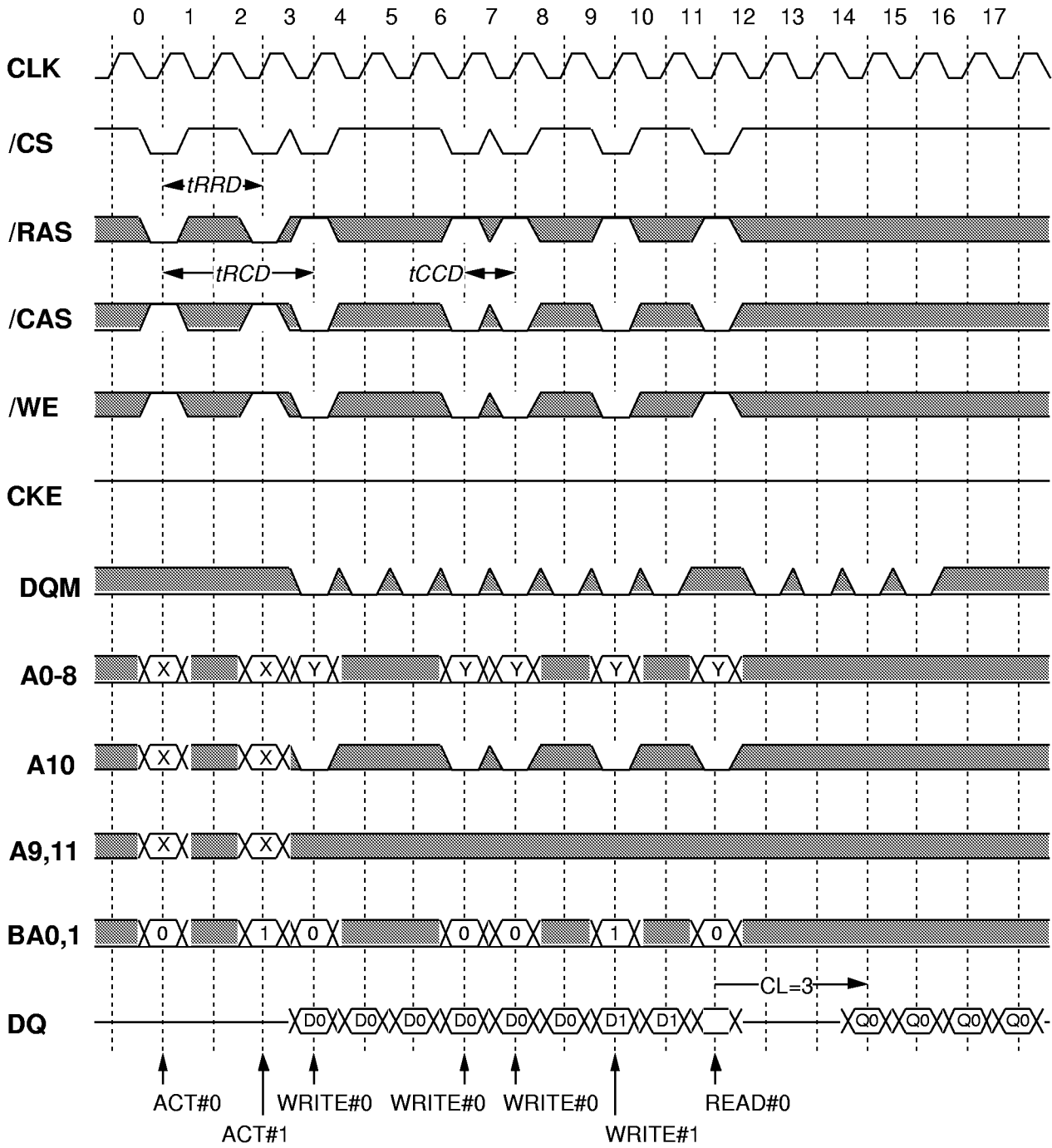


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Write Interrupted by Write / Read @BL=4



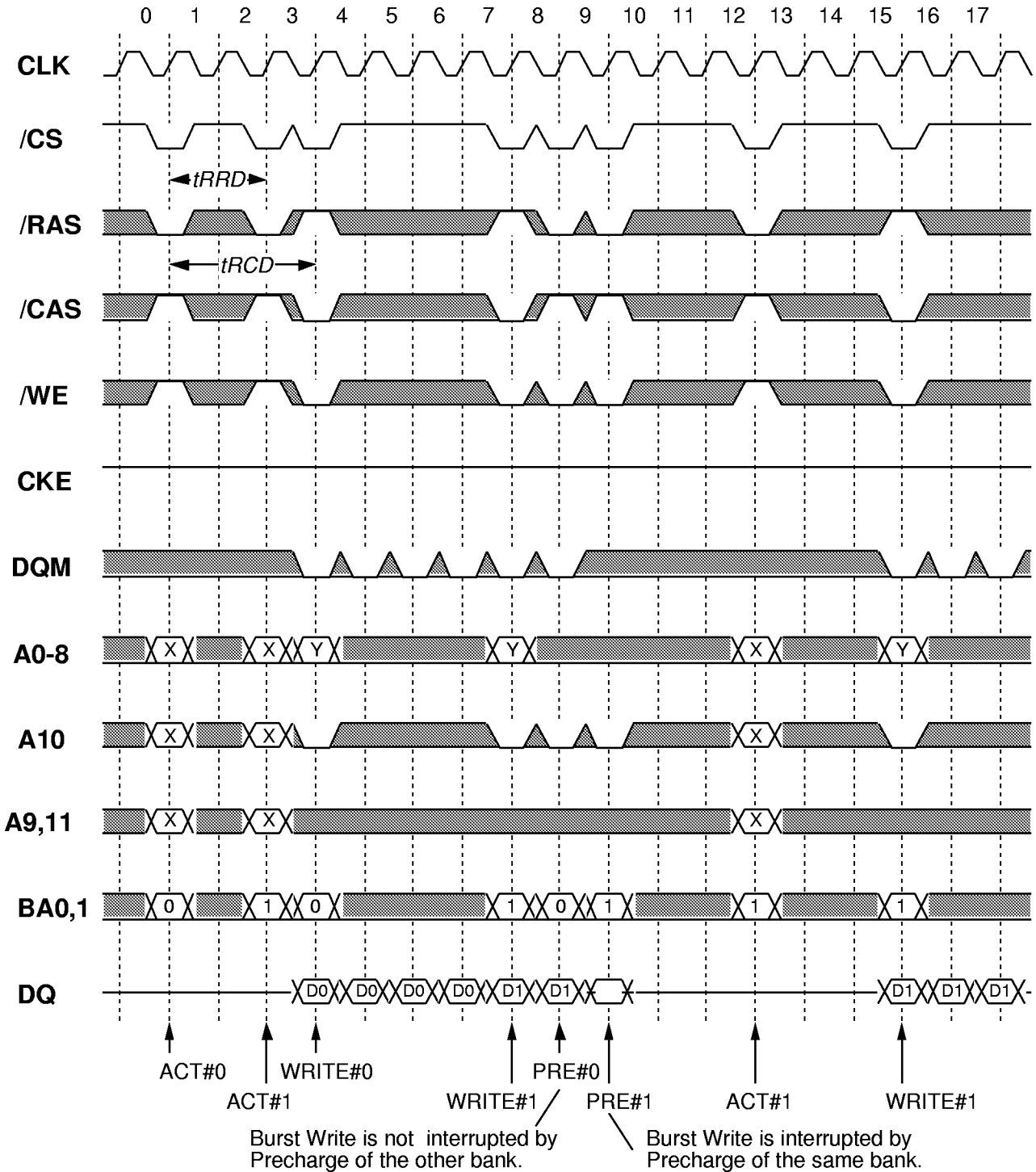
Burst Write can be interrupted by Write or Read of any active bank.

Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Write Interrupted by Precharge @BL=4

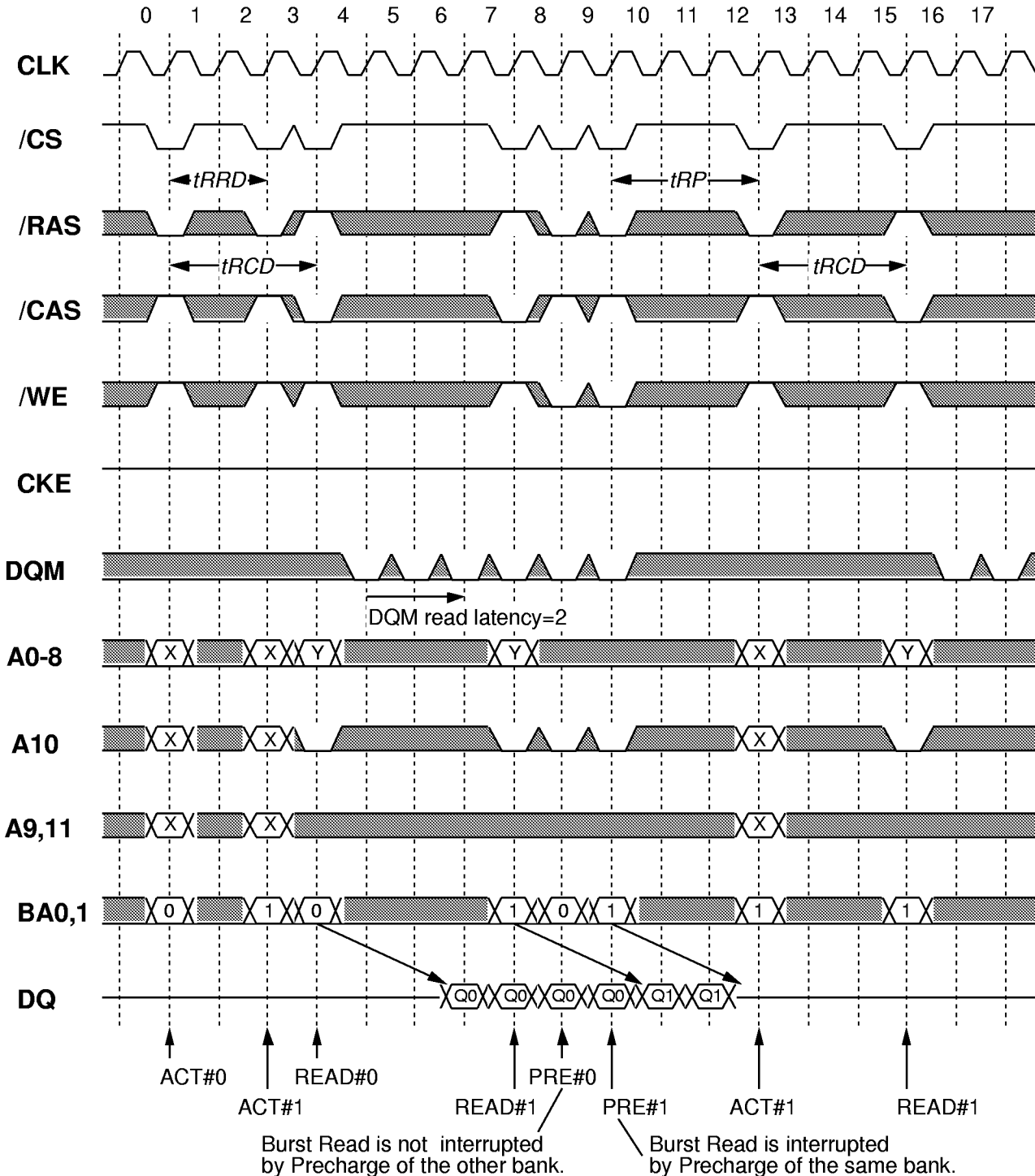


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Read Interrupted by Precharge @BL=4 CL=3

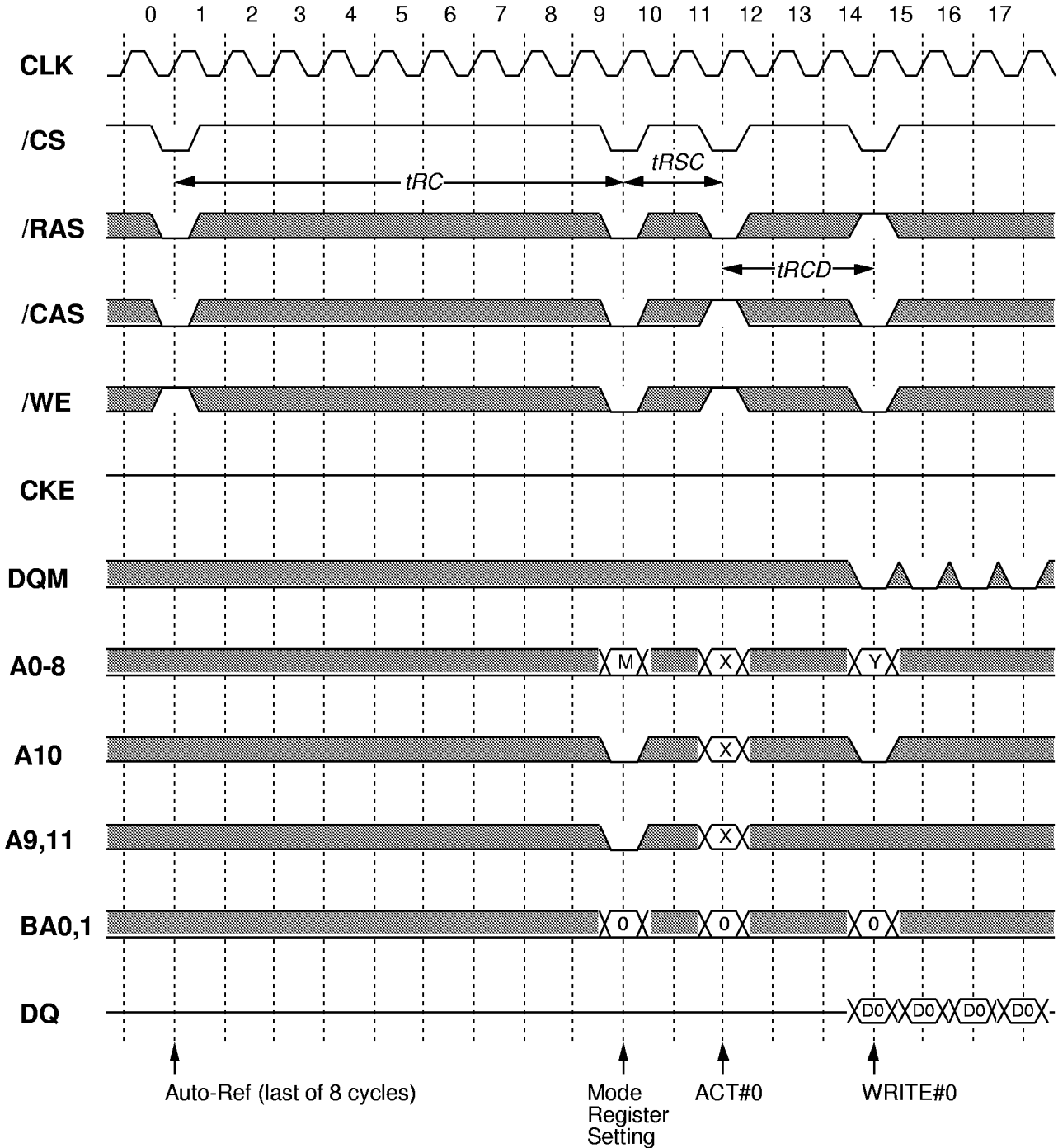


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Mode Register Setting

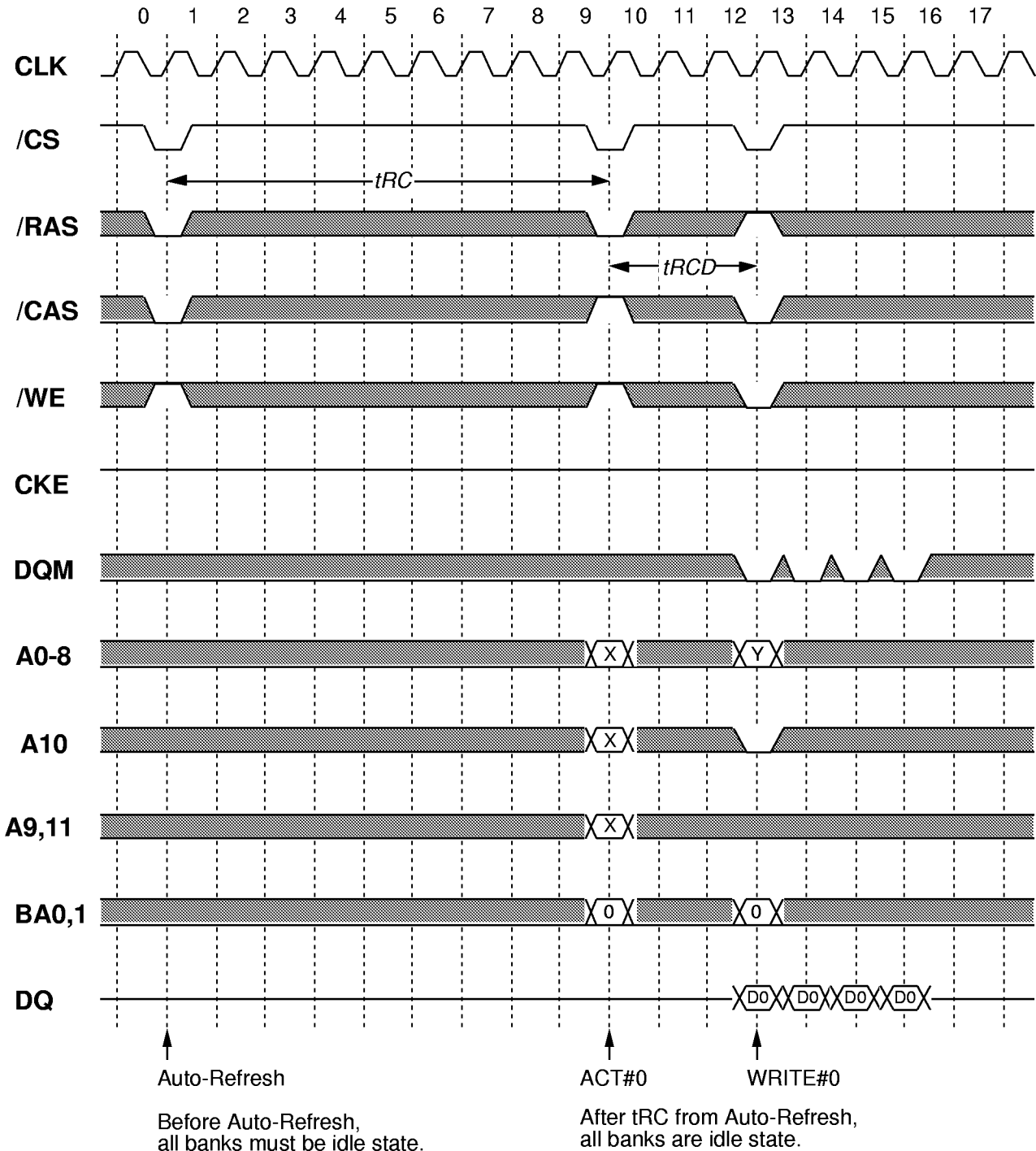


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Auto-Refresh @BL=4

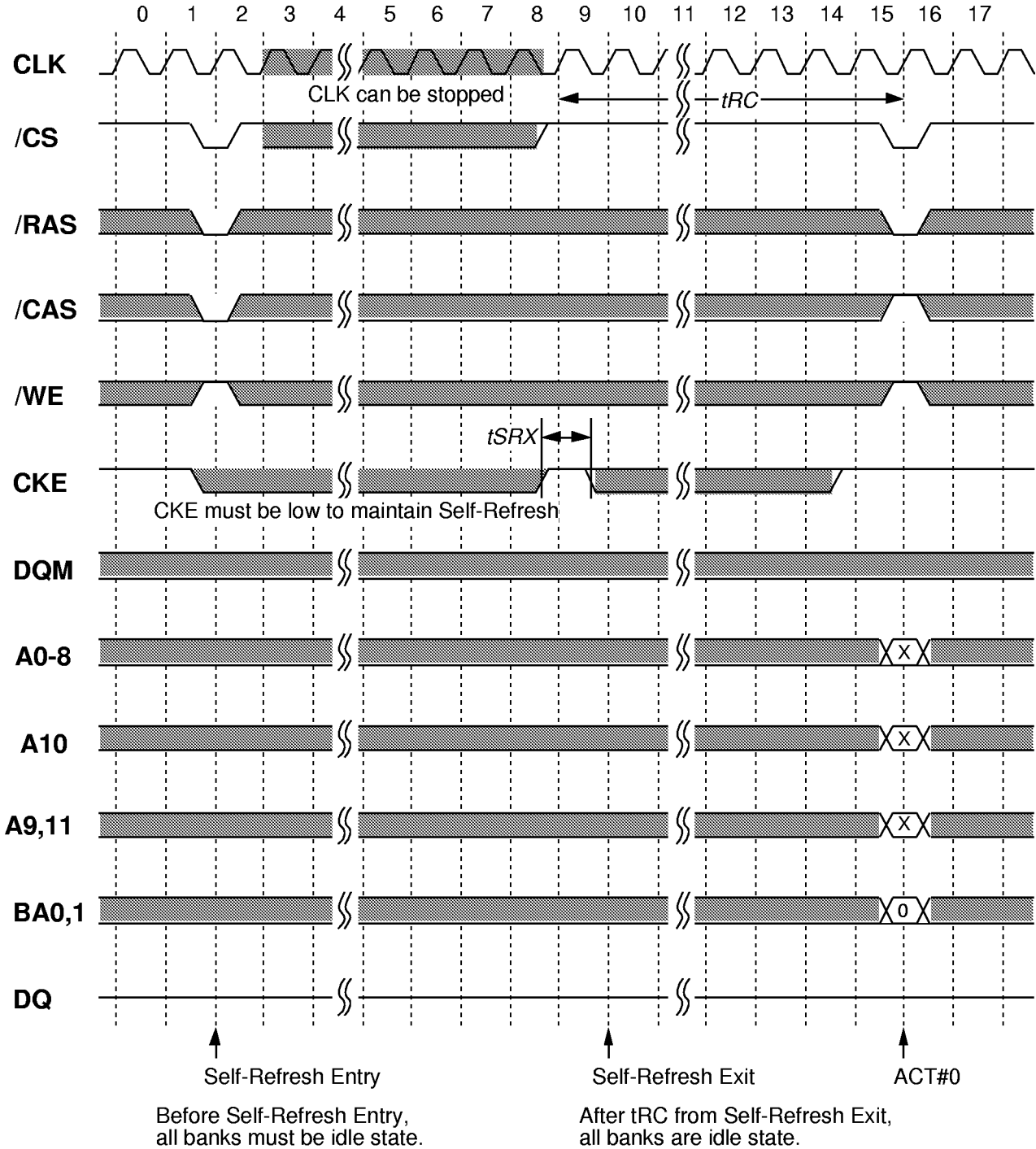


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Self-Refresh

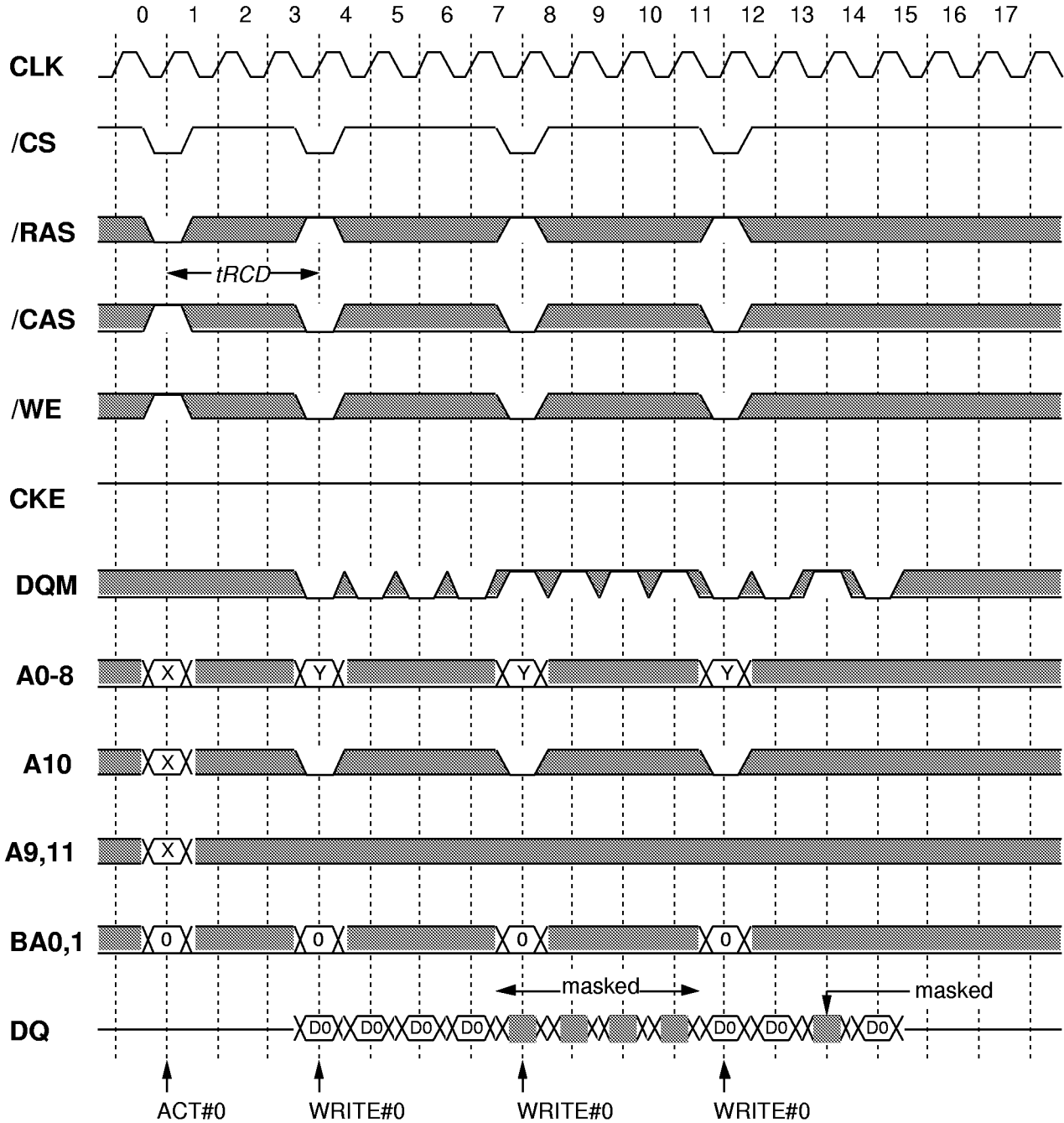


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

DQM Write Mask @BL=4

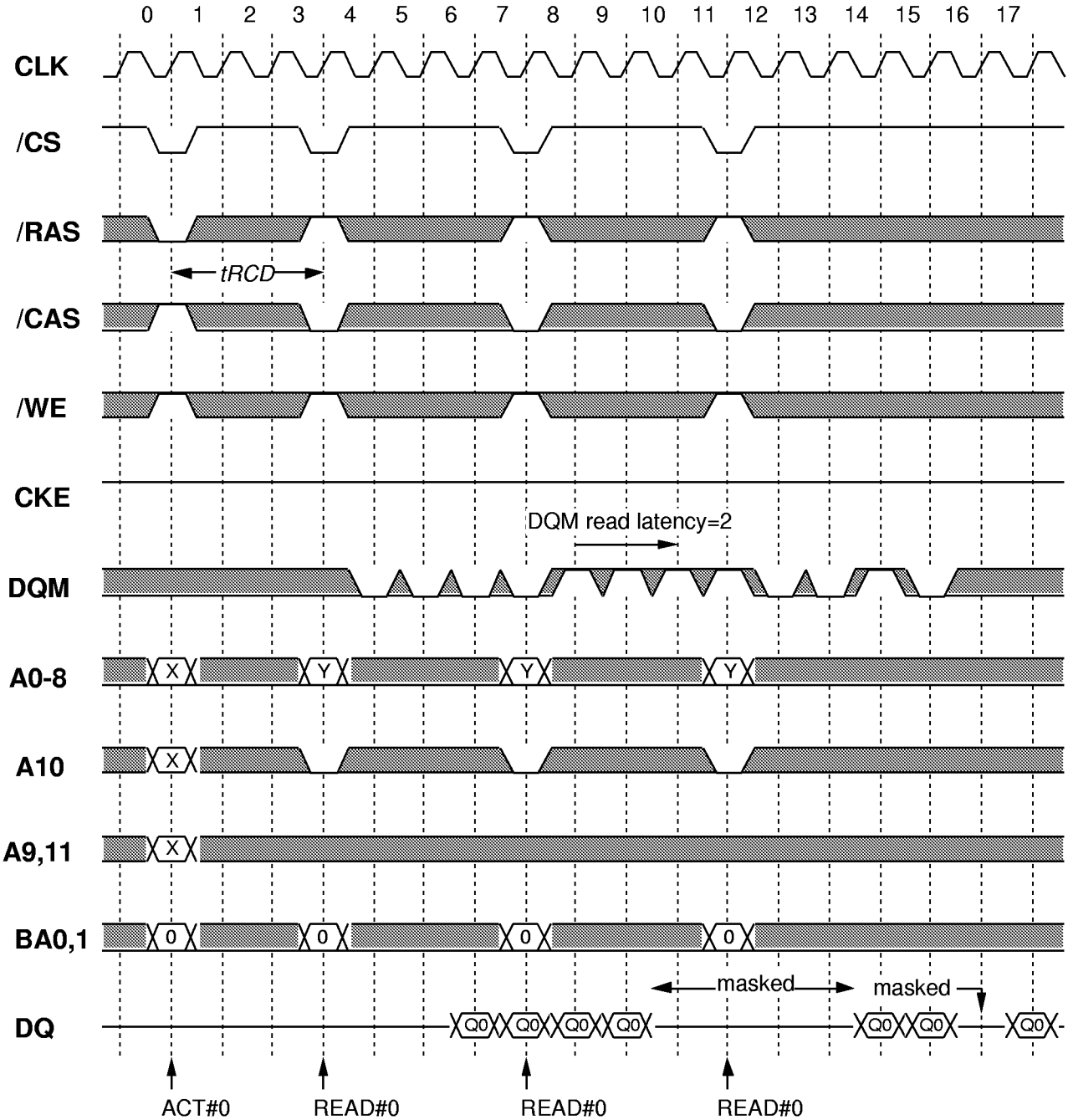


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

DQM Read Mask @BL=4 CL=3

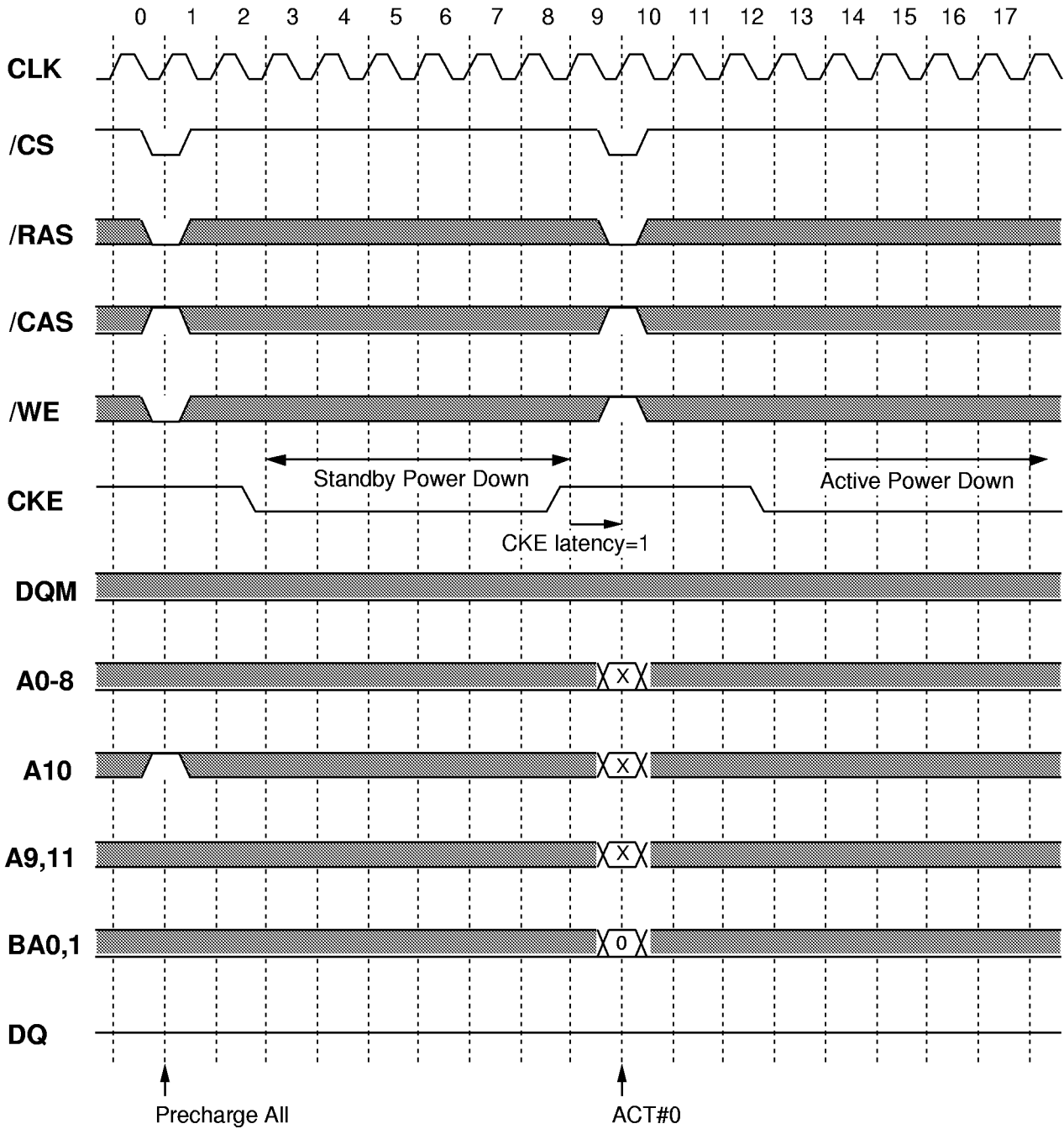


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

Power Down

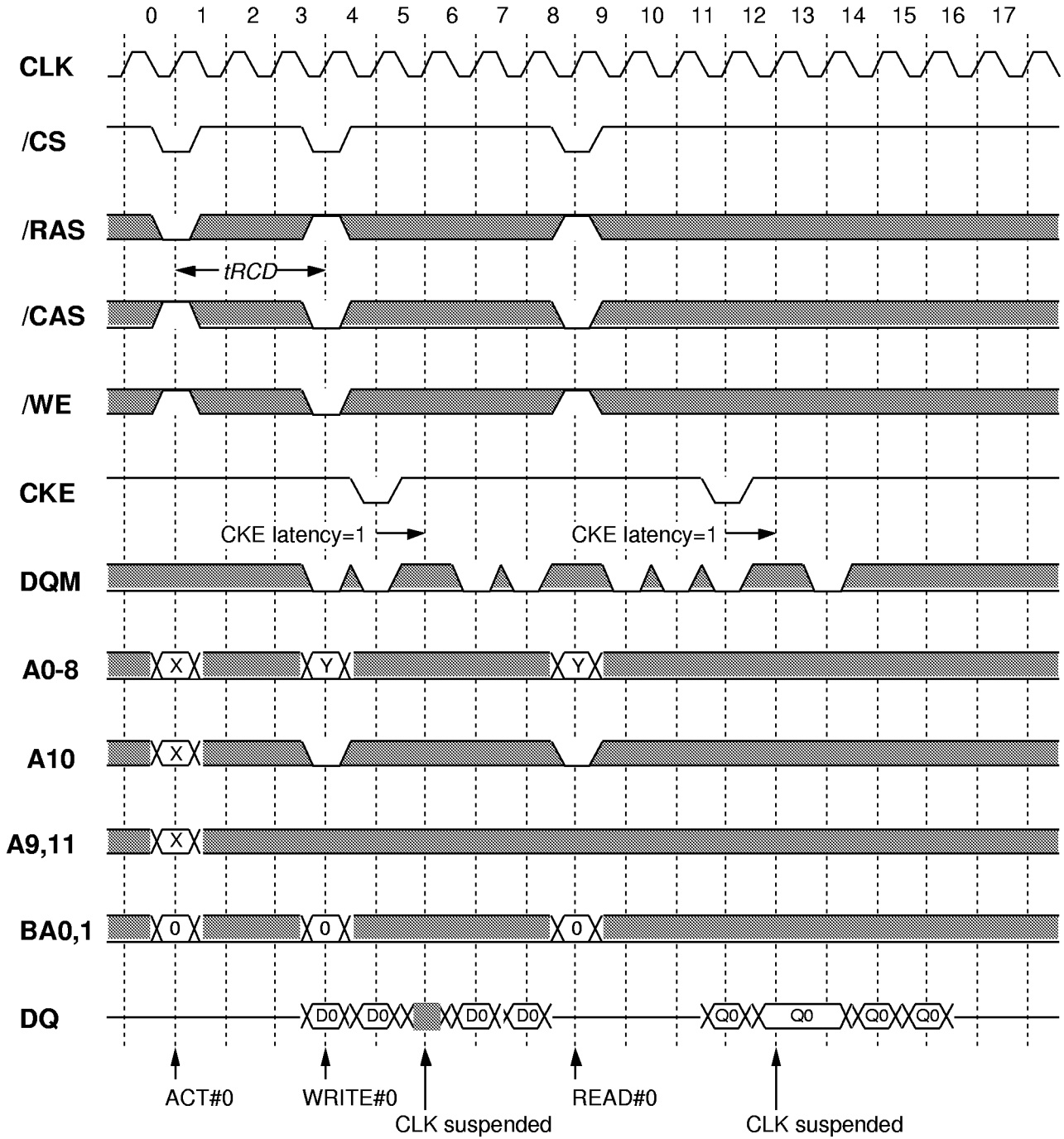


Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

CLK Suspend @BL=4 CL=3



Italic parameter indicates minimum case

MH8S64AKD -8,-10,-8L,-10L

536870912-BIT 8388608 - WORD BY 64-BIT)SynchronousDRAM

OUTLINE

